

Hawke Intel Discrete Block Diagram

CLK GEN
ICS9LPRS365 4

Intel Mobile CPU
Merom 4M
FSB:667 or 800 MHz
5, 6, 7

Project code : 91.4W101.001
PCB P/N : 48.4W101.011
PCB No. : 07212
Revision : -1

VRAM
16Mbx32x2 51

VRAM
16Mbx32x2 52

CRT 17
RGB CRT
LCD 18
LVDS
HDMI 16
HDMI
S-Video
SVIDEO

nVidia NB8P
(256MB)
OR
nVidia NB8M
(128MB)
47, 48, 49, 50

Crestline-PM
AGTL+ CPU I/F
DDR Memory I/F
EXTERNAL GRAPHICS
8, 9, 10, 11, 12, 13

DDR II 667 Channel A
DDR II 667 Channel B
DDR II 533/667 Slot 1 14
DDR II 533/667 Slot 2 15

Power SW
TI TPS2231 27

New Card 27

PCIE x 1
10/100 NIC
Marvell 88E8040 26

RJ45 CONN 27

1394 25
SD/SDIO/MMC
MS/MS Pro/XD
1394
Ricoh
R5C833
CardReader 24, 25

INTEL
ICH8-M
10 USB 2.0/1.1 ports
6 PCI Express ports
High Definition Audio
ATA 66/100
SATA
ACPI 1.1
LPC I/F
PCI/PCI BRIDGE
19, 20, 21, 22

PCIE x 1
PCIE x 1
PCIE x 2 & USB 2.0 x 2
Mini-Card x 1
802.11a/b/g 28
Mini-Card x 2
WWAN&BT&Robson 29

VGA DC/DC
TPS5117 53
INPUTS OUTPUTS
DCBATOUT VCC_GFX_CORE_S0

CPU DC/DC
ISL6262A 40
INPUTS OUTPUTS
DCBATOUT VCC_CORE

HP2
HEADPHONE
AMP
MAX4411 32

MIC IN
Azalia
CODEC
Sigmatel
STAC 9228 31
Digital Mic Array

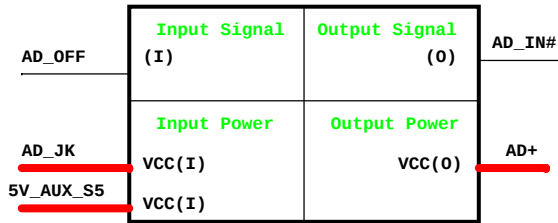
HP1
OP AMP
MAX9789A 32
2CH
SPEAKER

KBC
Winbond WPC8763L 33
SATA
PATA
HDD 23
ODD 23
Capacity Button 30
Touch Pad 36
Int. KB 36
S/W CIR 30
Thermal & Fan G792 35
Flash ROM 2MB 30

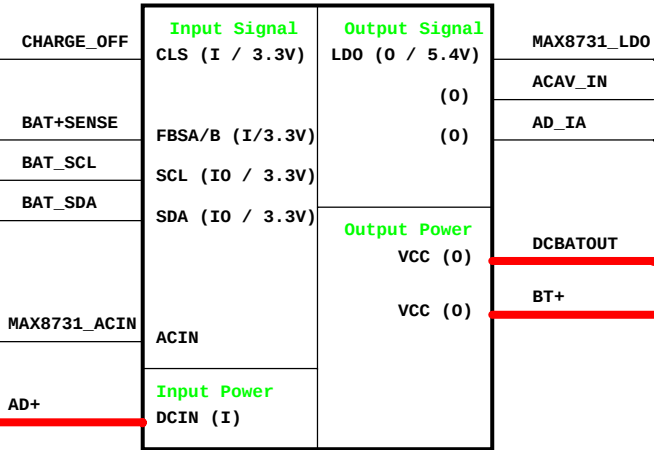
USB 2.0 x 1
USB 2.0 x 1
USB 2.0 x 1
USB 2.0 x 3
Camera 18
Biometric reader 30
Bluetooth 2.1 30
Left Side: USB x 2 37
Right Side: USB x 1 34

PCB LAYER
L1: TOP
L2: GND
L3: Signal
L4: Signal
L5: VCC
L6: Singal
L7: GND
L8: BOT

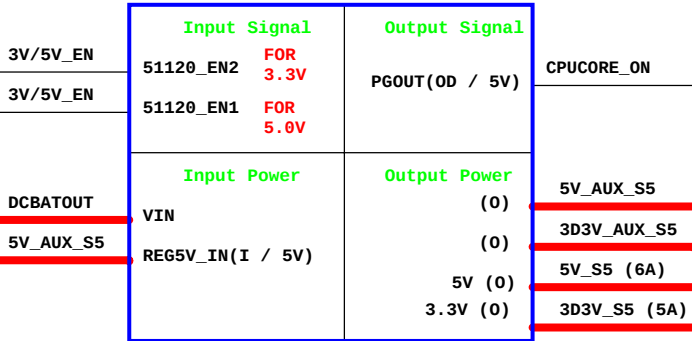
Adapter



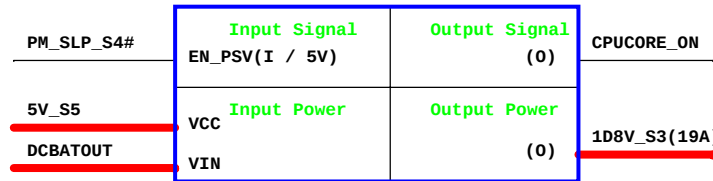
Charger MAX8731A



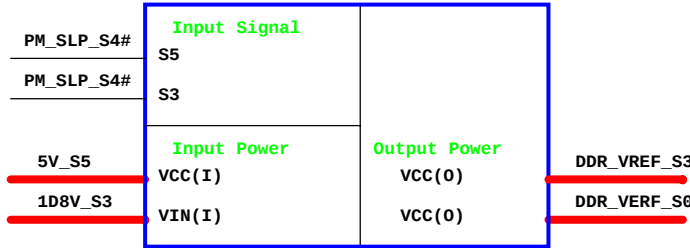
TI TPS51120 3D3V/5V



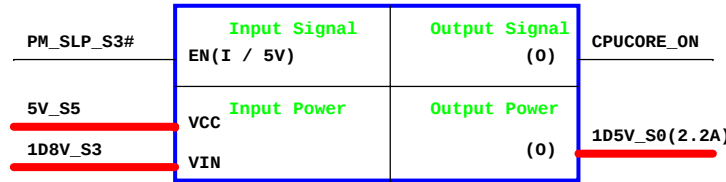
TPS51117 1D8V



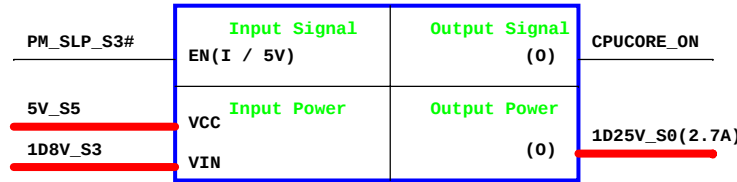
TI TPS51100 0.9V/DDR_VREF_S3



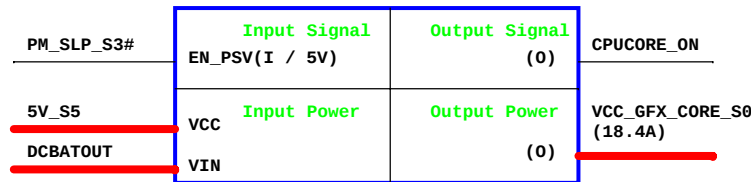
RT9018A 1D5V



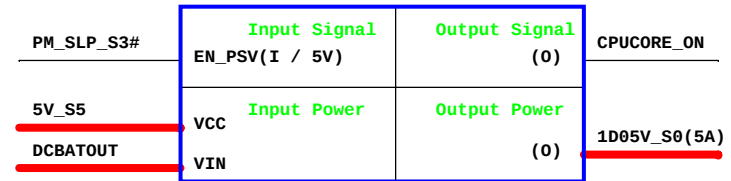
RT9018A 1D25V



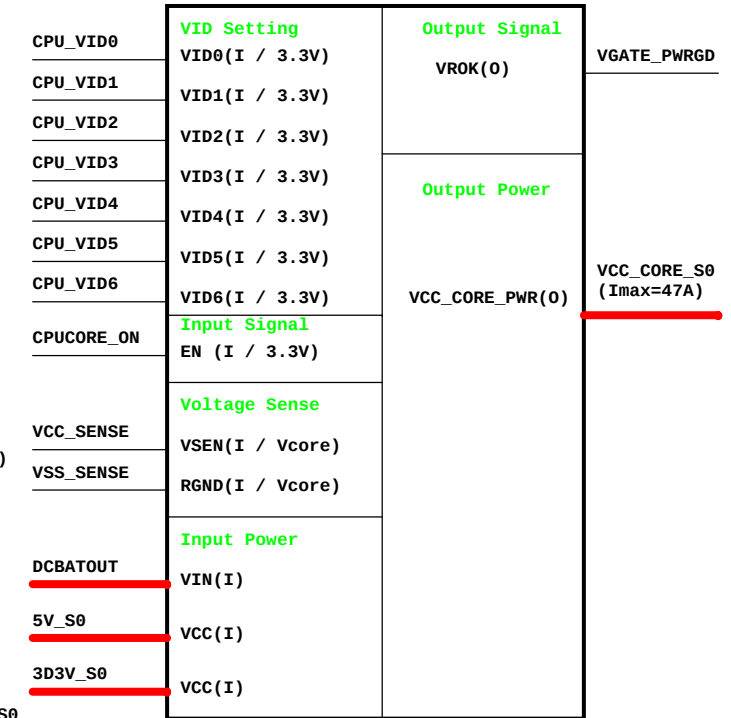
TPS51117 VGA_CORE



TPS51117 1D05V



ISL6262A CPU_CORE



<Core Design>

INTEL ICH8-M STRAP PIN

Signal	Usage/When Sampled	Comment
HDA_SDOUT	XOR Chain Entrance/ PCIE Port Config 1 bit1, Rising Edge of PWROK	Allows entrance to XOR Chain testing when TP3 pulled low at rising edge of PWROK.When TP3 not pulled low at rising edge of PWROK,sets bit1 of RPC.PC(Config Registers:offset 224h)
HDA_SYNC	PCIE Port Config 1 bit0, Rising Edge of PWROK.	Sets bit0 of RPC.PC(Config Registers:Offset 224h)
GNT2#	PCIE Port Config 2 bit0, Rising Edge of PWROK.	Sets bit2 of RPC.PC(Config Registers:Offset 224h)
GPI020	Reserved	Weak Internal PULL-DOWN.NOTE:This signal should not be pull HIGH.
GNT3#	Top-Block Swap Override. Rising Edge of PWROK.	Sampled low:Top-Block Swap mode(inverts A16 for all cycles targeting FWB BIOS space). Note: Software will not be able to clear the Top-Swap bit until the system is rebooted without GNT3# being pulled down.
GNT0# SPI_CS1#	Boot BIOS Destination Selection. Rising Edge of PWROK.	Controllable via Boot BIOS Destination bit (Config Registers:Offset 3410h:bit 11:10). GNT0# is MSB, 01-SPI, 10-PCI, 11-LPC.
INTVRMEN	Integrated VccSus1_05 VccSus1_5 and VccCL1_5 VRM Enable/Disable.Always sampled.	Enables integrated VccSus1_05,VccSus1_5 and VccCL1_5 VRM when sampled high
LAN100_SLP	Integrated VccLAN1_05 VccCL1_05 VRM enable /Disable. Always sampled.	Enables integrated VccLAN1_05,VccCL1_05 VRM when sampled high
SATALED#	PCIE LAN REVERSAL.Rising Edge of PWROK.	This signal has weak internal pull-up. set bit27 of MPC.LR(Device28:Function0:Offset D8)
SPKR	No Reboot. Rising Edge of PWROK.	If sampled high, the system is strapped to the "No Reboot" mode(ICH8M will disable the TCO Timer system reboot feature). The status is readable via the NO REBOOT bit.(Offset:3410h:bit5)
TP3	XOR Chain Entrance. Rising Edge of PWROK.	This signal should not be pull low unless using XOR Chain testing.
GPI033/ HDA_DOCK_EN#	Flash Descriptor Security Override Strap Rising Edge of PWROK.	Internal Pull-Up.If sampled low,the Flash Descriptor Security will be overridden.if high,the Security measures defined in the Flash Descriptor will be in effect. This should only be used in manufacturing environments

XOR Chain Entrance Strap			
ICH_RSVDTP3	AZ_DOUT ICH	Description	
0	0	RSVD	
0	1	Enter XOR Chain	
1	0	Normal Operation(default)	
1	1	Set PCIE port cofig bit1	

A16 swap override strap		
PCI_GNT#3	low = A16 swap override enable	
	high = default	
BOOT BIOS Strap		
PCI_GNT#0	SPI_CS#1	BOOT BIOS Location
0	1	SPI
1	0	PCI
1	1	LPC(Default)

Integrated VccSus1_05,VccSus1_5,VccCL1_5		
SM_INTVRMEN	High=Enable	Low=Disable
Integrated VccLan1_05VccCL1_05		
LAN100_SLP	High=Enable	Low=Disable

DEFAULE HIGH

No Reboot Strap	
SPKR	LOW = Defaule
	High=No Reboot

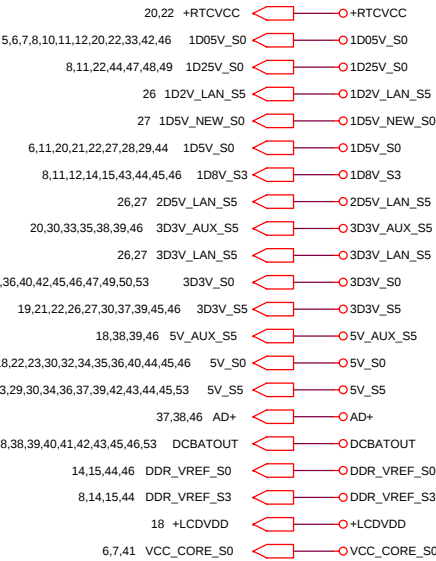
8.2K PULL HIGH

INTEL ICH8-M INTEGRATED PULL-UPS and PULL-DOWNS

SIGNAL	Resistor Type/Value
HDA_BIT_CLK	PULL-DOWN 20K
HDA_RST#	NONE
HDA_SDIN[3:0]	PULL-DOWN 20K
HDA_SDOUT	PULL-DOWN 20K
HDA_SYNC	PULL-DOWN 20K
GNT[3:0]	PULL-UP 20K
GPI0[20]	PULL-DOWN 20K
LDA[3:0]#/FWH[3:0]#	PULL-UP 20K
LAN_RXD[2:0]	PULL-UP 20K
LDRQ[0]	PULL-UP 20K
LDRQ[1]/GPI023	PULL-UP 20K
PME#	PULL-UP 20K
PWRBTN#	PULL-UP 20K
SATALED#	PULL-UP 20K
SPI_CS1#	PULL-UP 20K
SPI_CLK	PULL-UP 20K
SPI_MOSI	PULL-UP 20K
SPI_MISO	PULL-UP 20K
TACH_[3:0]	PULL-UP 20K
SPKR	PULL-DOWN 20K
TP[3]	PULL-UP 20K
USB[9:0][P,N]	PULL-DOWN 15K
CL_RST#	TBD

INTEL CRESTLINE STRAP PIN

CFG Strap	LOW 0	HIGH 1
CFG 5	DMI X 2	DMI X 4 ★
CFG 8 Low Power PCI Express	Normal★	Low Power mode
CFG 9 PCI Express Graphics Lane Reversal	Lane Reversal	Normal Mode(Lanes number in order)★
CFG 16 PSB dynamic ODT	Disabled	Enabled ★
CFG 19 DMI Lane Reserved	Normal Operation ★	Reserved Lane
CFG 20 Concurrent SDVO/PCIE	Only PCIE or SDVO is operation★	PCIE and SDVO are operation simultaneous
SDVO_CTRL_DATA SDVO Present	No SDVO Card Present ★	SDVO Card Present
CFG 12 CFG 13	XOR/ALL-Z	
LL(00)	Reserved	
LH(01)	XOR Mode Enabled	
HL(10)	All Z Mode Enabled	
HH(11)	Normal Operation	



PCI ROUTING

	IDSEL	INT	REQ	GNT
1394/ MediaCard	AD25	A D	0	0

USB TABLE

USB0	Ext Lift Side (Bottom)
USB1	Ext Lift Side (Top)
USB2	Ext Right Side
USB3	N/A
USB4	WWAN
USB5	Bluetooth
USB6	Camera
USB7	Biometric
USB8	Express Card
USB9	3rd mini card

PCIE Routing

LANE1	10/100M Bit LOM
LANE2	MiniCard WLAN
LANE3	MiniCard WWAN
LANE4	BT/UWB/Robson
LANE5	Express Card
LANE6	N/A

<Core Design>

緯創資通

Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Table of Content

Size A3

Document Number

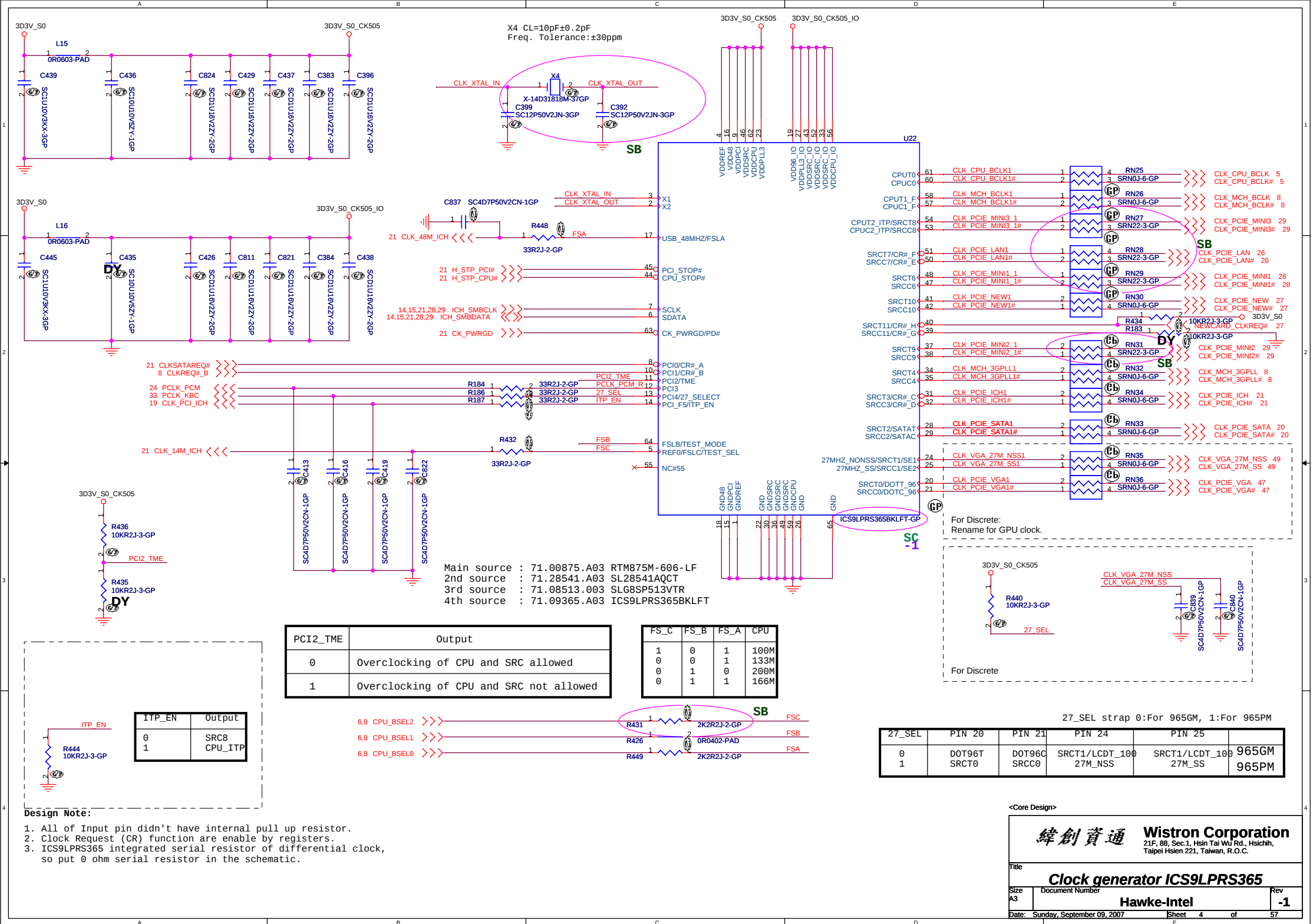
Rev

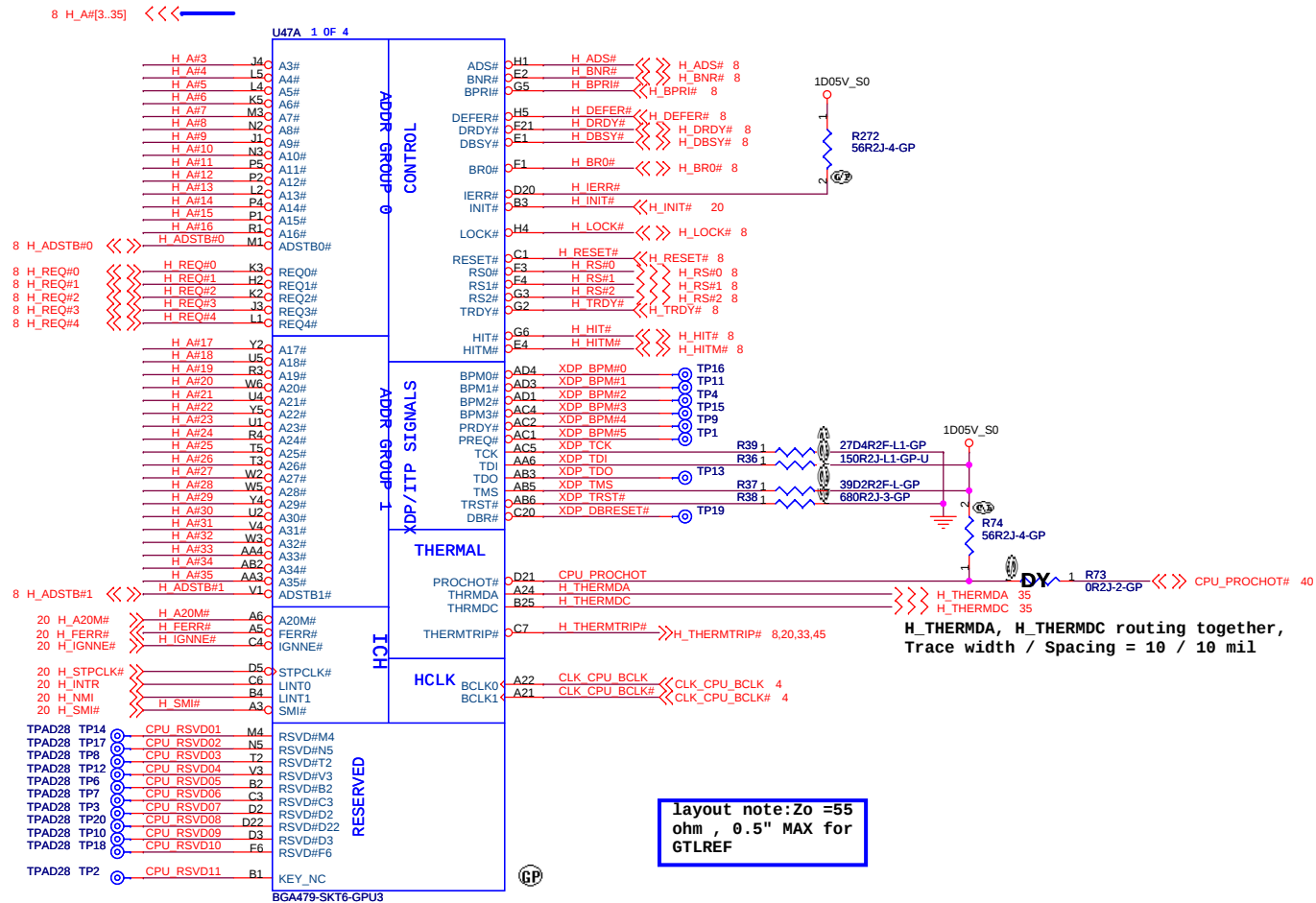
Date: Sunday, September 09, 2007

Sheet 3 of 57

Hawke-Intel

-1





Main source : 62.10079.021 Tyco 2-1871873-4
2nd source : 62.10040.221 Foxconn PZ47827-274M-41

<Core Design>

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title Meron(1/3)-AGTL+/XDP
Size A3 Document Number Hawke-Intel Rev -1
Date: Sunday, September 09, 2007 Sheet 5 of 57

8 H_D#[0.63] <<>>



8 H_DSTBN#0
8 H_DSTBP#0
8 H_DINV#0

8 H_DSTBN#1
8 H_DSTBP#1
8 H_DINV#1

4.8 CPU_BSEL0
4.8 CPU_BSEL1
4.8 CPU_BSEL2

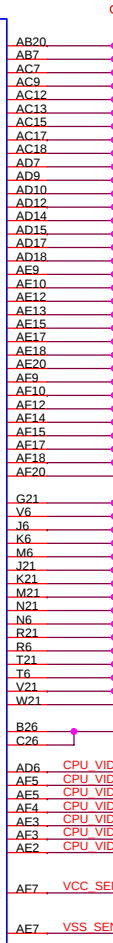
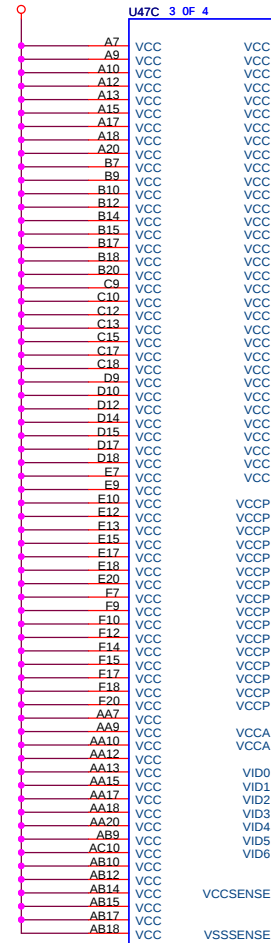
PLACE C617 close to the TEST4 PIN,
make sure TEST3,TEST4,TEST5 trace
routing is reference to GND and
away other noisy signals

CPU_BSEL	CPU_BSEL2	CPU_BSEL1	CPU_BSEL0
166	0	1	1
200	0	1	0

Resistor Placed
within 0.5" of CPU
pin. Trace should
be at least 25 mils
away from any other
toggling signal .
COMP[0,2] trace
width is 18 mils.
COMP[1,3] trace
width is 4 mils .

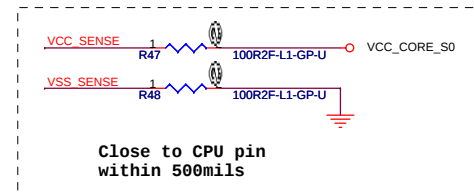
VCC_CORE_S0

VCC_CORE_S0



layout note:
place C618 near
PIN B26

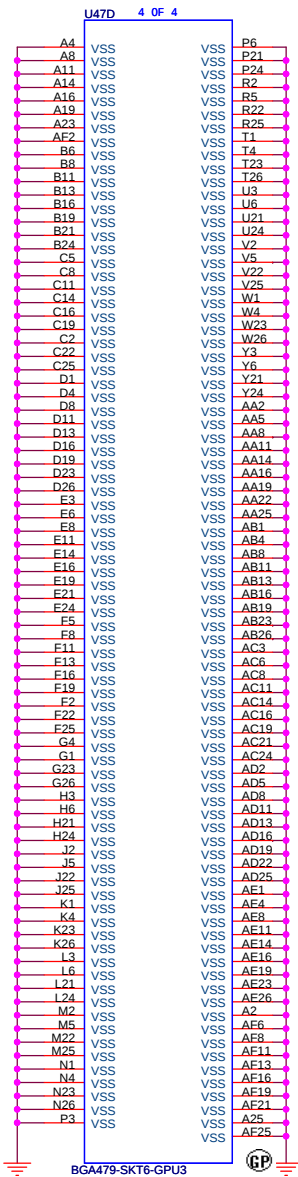
Length match within
25 mils . The trace
width/space/other is
20/7/25 .



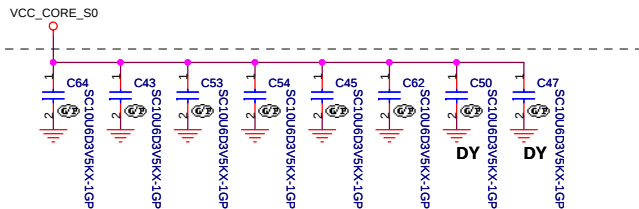
<Core Design>

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

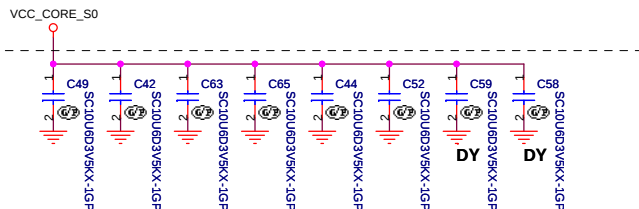
Title			Rev
Meron(2/3)-AGTL+PWR			
Size	Document Number	Hawke-Intel	
A3		-1	
Date:	Sunday, September 09, 2007	Sheet	6 of 57



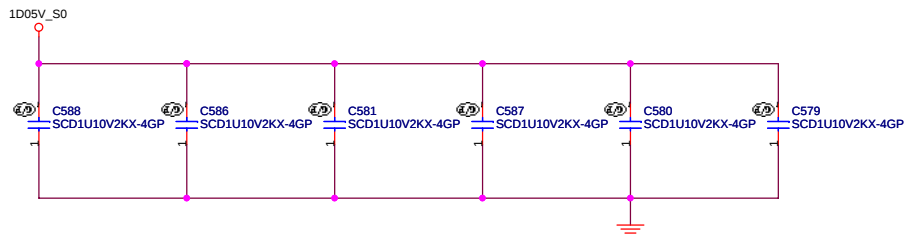
Place these capacitors on L1
(North side ,Secondary Layer)



Place these capacitors on L1
(North side ,Secondary Layer)



Mid Frequncd
Decoupling



Place these
inside socket
cavity on L1
(North side
Secondary)

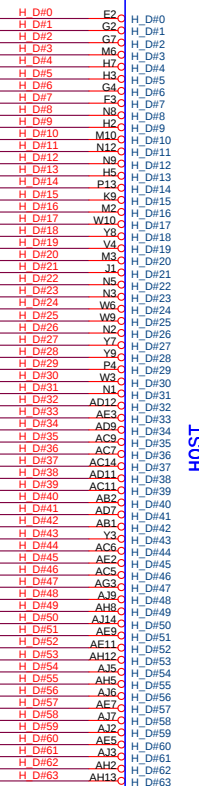
<Core Design>

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title
Meron(3/3)-GND&Bypass
Size A3 Document Number
Hawke-Intel Rev
-1
Date: Sunday, September 09, 2007 Sheet 7 of 57

6 H_D#0[0.63]

U57A 1 OF 18



HOST

H_ADS#

H_ADSB#0

H_ADSB#1

H_ADSB#2

H_ADSB#3

H_ADSB#4

H_ADSB#5

H_ADSB#6

H_ADSB#7

H_ADSB#8

H_ADSB#9

H_ADSB#10

H_ADSB#11

H_ADSB#12

H_ADSB#13

H_ADSB#14

H_ADSB#15

H_ADSB#16

H_ADSB#17

H_ADSB#18

H_ADSB#19

H_ADSB#20

H_ADSB#21

H_ADSB#22

H_ADSB#23

H_ADSB#24

H_ADSB#25

H_ADSB#26

H_ADSB#27

H_ADSB#28

H_ADSB#29

H_ADSB#30

H_ADSB#31

H_ADSB#32

H_ADSB#33

H_ADSB#34

H_ADSB#35

H_ADSB#36

H_ADSB#37

H_ADSB#38

H_ADSB#39

H_ADSB#40

H_ADSB#41

H_ADSB#42

H_ADSB#43

H_ADSB#44

H_ADSB#45

H_ADSB#46

H_ADSB#47

H_ADSB#48

H_ADSB#49

H_ADSB#50

H_ADSB#51

H_ADSB#52

H_ADSB#53

H_ADSB#54

H_ADSB#55

H_ADSB#56

H_ADSB#57

H_ADSB#58

H_ADSB#59

H_ADSB#60

H_ADSB#61

H_ADSB#62

H_ADSB#63

H_DIN#0

H_DIN#1

H_DIN#2

H_DIN#3

H_DIN#4

H_DIN#5

H_DIN#6

H_DIN#7

H_DIN#8

H_DIN#9

H_DIN#10

H_DIN#11

H_DIN#12

H_DIN#13

H_DIN#14

H_DIN#15

H_DIN#16

H_DIN#17

H_DIN#18

H_DIN#19

H_DIN#20

H_DIN#21

H_DIN#22

H_DIN#23

H_DIN#24

H_DIN#25

H_DIN#26

H_DIN#27

H_DIN#28

H_DIN#29

H_DIN#30

H_DIN#31

H_DIN#32

H_DIN#33

H_DIN#34

H_DIN#35

H_DIN#36

H_DIN#37

H_DIN#38

H_DIN#39

H_DIN#40

H_DIN#41

H_DIN#42

H_DIN#43

H_DIN#44

H_DIN#45

H_DIN#46

H_DIN#47

H_DIN#48

H_DIN#49

H_DIN#50

H_DIN#51

H_DIN#52

H_DIN#53

H_DIN#54

H_DIN#55

H_DIN#56

H_DIN#57

H_DIN#58

H_DIN#59

H_DIN#60

H_DIN#61

H_DIN#62

H_DIN#63

H_DSTB#0

H_DSTB#1

H_DSTB#2

H_DSTB#3

H_DSTB#4

H_DSTB#5

H_DSTB#6

H_DSTB#7

H_DSTB#8

H_DSTB#9

H_DSTB#10

H_DSTB#11

H_DSTB#12

H_DSTB#13

H_DSTB#14

H_DSTB#15

H_DSTB#16

H_DSTB#17

H_DSTB#18

H_DSTB#19

H_DSTB#20

H_DSTB#21

H_DSTB#22

H_DSTB#23

H_DSTB#24

H_DSTB#25

H_DSTB#26

H_DSTB#27

H_DSTB#28

H_DSTB#29

H_DSTB#30

H_DSTB#31

H_DSTB#32

H_DSTB#33

H_DSTB#34

H_DSTB#35

H_DSTB#36

H_DSTB#37

H_DSTB#38

H_DSTB#39

H_DSTB#40

H_DSTB#41

H_DSTB#42

H_DSTB#43

H_DSTB#44

H_DSTB#45

H_DSTB#46

H_DSTB#47

H_DSTB#48

H_DSTB#49

H_DSTB#50

H_DSTB#51

H_DSTB#52

H_DSTB#53

H_DSTB#54

H_DSTB#55

H_DSTB#56

H_DSTB#57

H_DSTB#58

H_DSTB#59

H_DSTB#60

H_DSTB#61

H_DSTB#62

H_DSTB#63

H_REQ#0

H_REQ#1

H_REQ#2

H_REQ#3

H_REQ#4

H_REQ#5

H_REQ#6

H_REQ#7

H_REQ#8

H_REQ#9

H_REQ#10

H_REQ#11

H_REQ#12

H_REQ#13

H_REQ#14

H_REQ#15

H_REQ#16

H_REQ#17

H_REQ#18

H_REQ#19

H_REQ#20

H_REQ#21

H_REQ#22

H_REQ#23

H_REQ#24

H_REQ#25

H_REQ#26

H_REQ#27

H_REQ#28

H_REQ#29

H_REQ#30

H_REQ#31

H_REQ#32

H_REQ#33

H_REQ#34

H_REQ#35

H_REQ#36

H_REQ#37

H_REQ#38

H_REQ#39

H_REQ#40

H_REQ#41

H_REQ#42

H_REQ#43

H_REQ#44

H_REQ#45

H_REQ#46

H_REQ#47

H_REQ#48

H_REQ#49

H_REQ#50

H_REQ#51

H_REQ#52

H_REQ#53

H_REQ#54

H_REQ#55

H_REQ#56

H_REQ#57

H_REQ#58

H_REQ#59

H_REQ#60

H_REQ#61

H_REQ#62

H_REQ#63

H_RS#0

H_RS#1

H_RS#2

H_RS#3

H_RS#4

H_RS#5

H_RS#6

H_RS#7

H_RS#8

H_RS#9

H_RS#10

H_RS#11

H_RS#12

H_RS#13

H_RS#14

H_RS#15

H_RS#16

H_RS#17

H_RS#18

H_RS#19

H_RS#20

H_RS#21

H_RS#22

H_RS#23

H_RS#24

H_RS#25

H_RS#26

H_RS#27

H_RS#28

H_RS#29

H_RS#30

H_RS#31

H_RS#32

H_RS#33

H_RS#34

H_RS#35

H_RS#36

H_RS#37

H_RS#38

H_RS#39

H_RS#40

H_RS#41

H_RS#42

H_RS#43

H_RS#44

H_RS#45

H_RS#46

H_RS#47

H_RS#48

H_RS#49

H_RS#50

H_RS#51

H_RS#52

H_RS#53

H_RS#54

H_RS#55

H_RS#56

H_RS#57

H_RS#58

H_RS#59

H_RS#60

H_RS#61

H_RS#62

H_RS#63

Layout note :

Route H_SCOMP# with trace width, spacing and impedance (55 ohm) same as FSB data traces

Layout Note :

H_RCOMP / H_VREF / H_SWNG trace width and spacing is 10/20

H_RCOMP

H_VREF

H_SWNG

H_RCOMP

H_VREF

H_SWNG

H_RCOMP

H_VREF

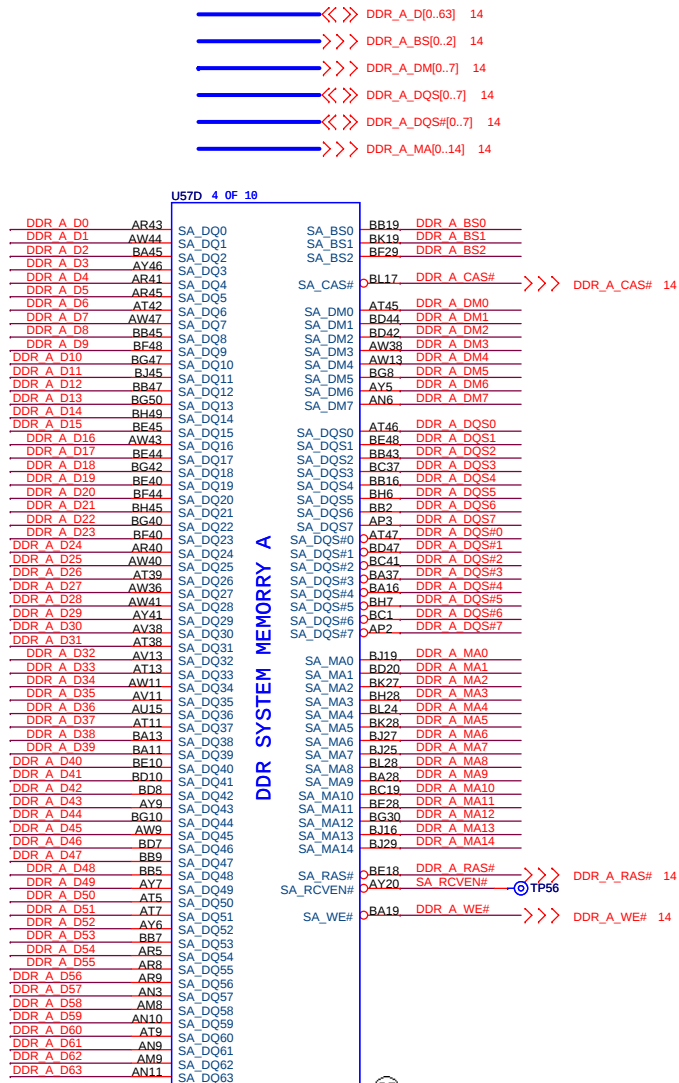
H_SWNG

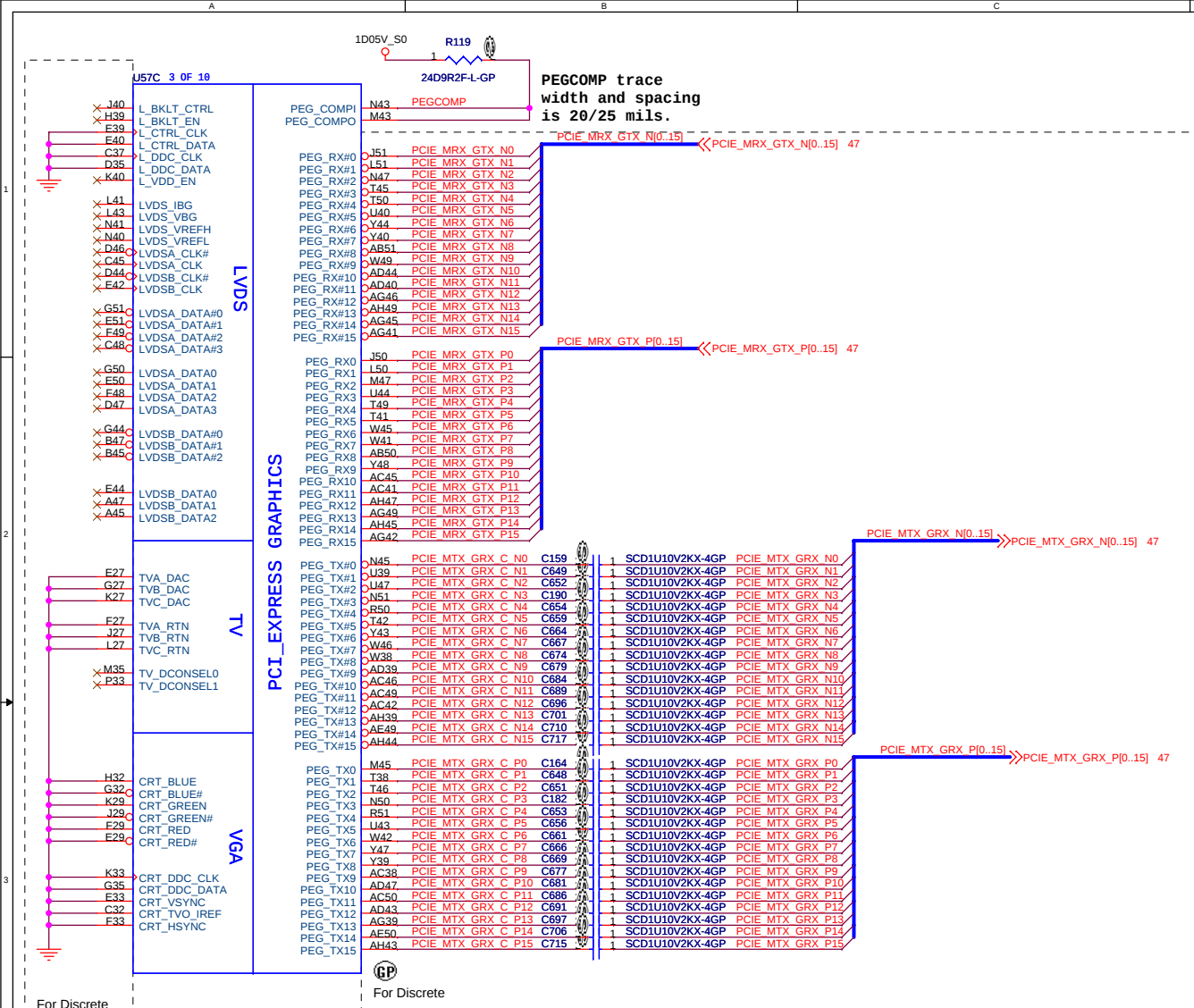
H_RCOMP

H_VREF

H_SWNG

H_RCOMP





Strap Pin Table

CFG[2:0] FSB Freq select

CFG5 (DMI select)

CFG6

CFG7 (CPU Strap)

CFG8 (Low power PCIE)

CFG9
(PCIE Graphics Lane Reversal)

CFG[11:10]

CFG[13:12] (XOR/ALLZ)

CFG[15:14]

CFG16 (FSB Dynamic ODT)

CFG[18:17]

SDVO_CTRLDATA

CFG19(DMI Lane Reversal)

CFG20(PCIE/SDVO consurrent)

010 = FSB 800MHZ
011 = FSB 667MHZ
Others = Reserved

0 = DMI x 2
1 = DMI x 4 *

Reserved

0 = Reserved
1 = Mobile CPU *

0 = Normal mode
1 = Low Power mode *

0 = Reverse Lane
1 = Normal Operation *

Reserved

00 = Reserved
01 = XOR Mode Enabled
10 = All Z Mode Enabled
11 = Normal Operation (Default) *

Reserved

0 = Disable
1 = Enable *

Reversed

0 = No SDVO Device Present *
1 = SDVO Device Present

0 = Normal Operation
(Lane number in Order) *
1 = Reverse lane

0 = Only PCIE or SDVO is operational *
1 = PCIE/SDVO are operating simu.

<Core Design>

緯創資通

Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

CRESTLINE(3/6)-VGA/LVDS/TV

Size
A3

Document Number

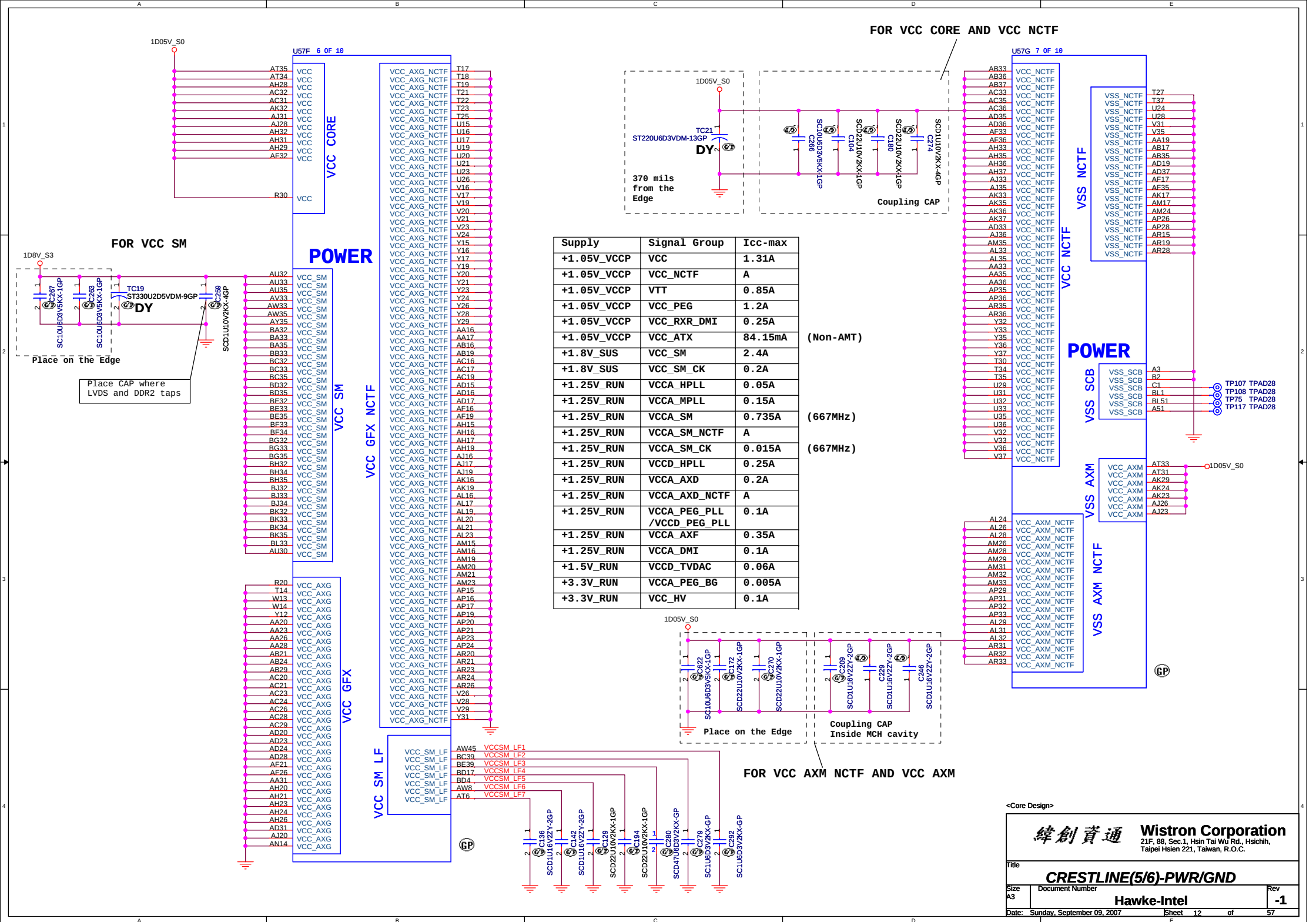
Hawke-Intel

Rev

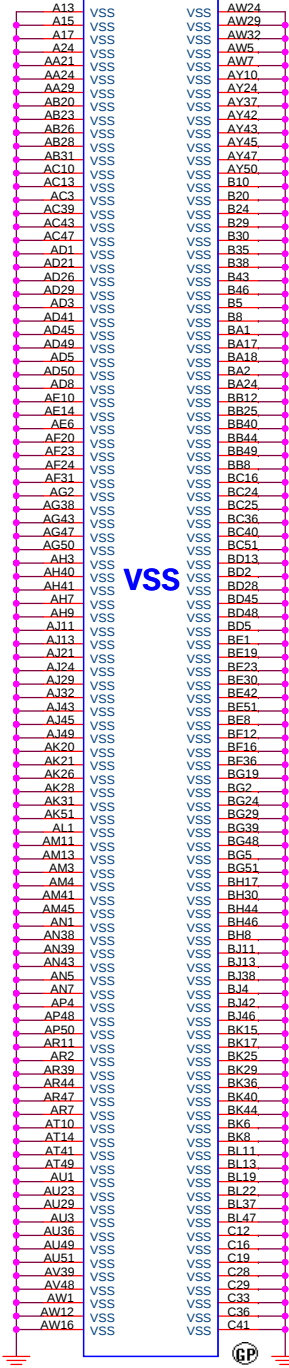
-1

Date: Sunday, September 09, 2007

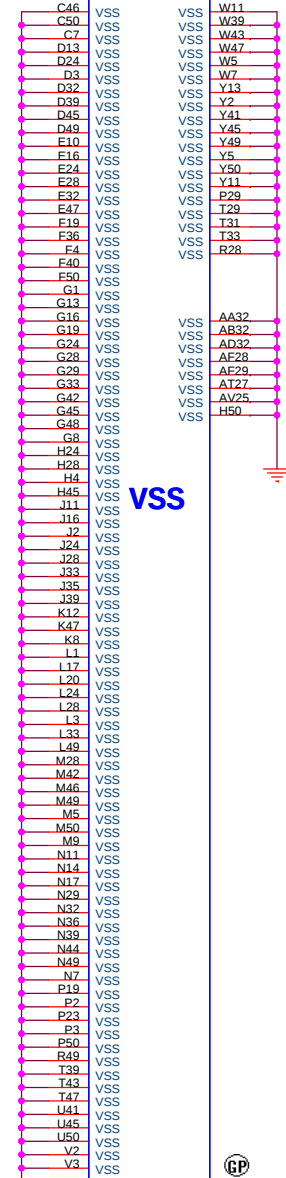
Sheet 10 of 57



U57I 9 OF 10



U57J10 OF 10

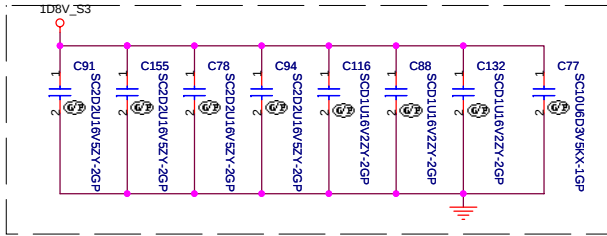


<Core Design>

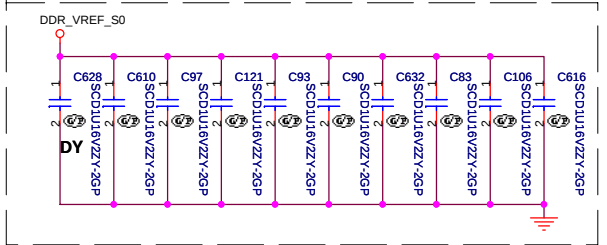
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title		
CRESTLINE(6/6)-PWR/GND		
Size	Document Number	Rev
A3	Hawke-Intel	-1
Date: Sunday, September 09, 2007		
Sheet 13 of 57		

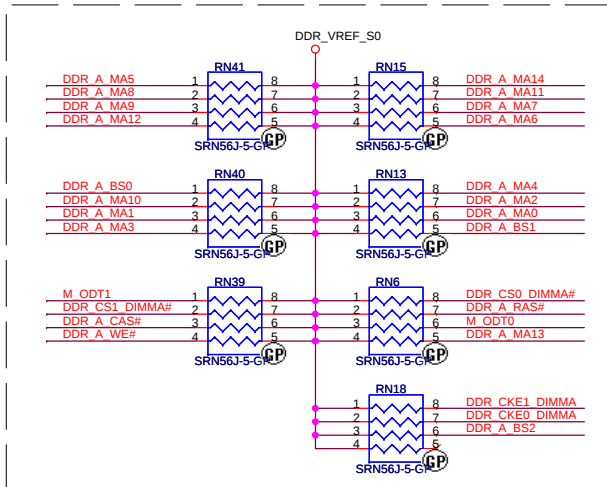
Layout Note:
Place near DM1



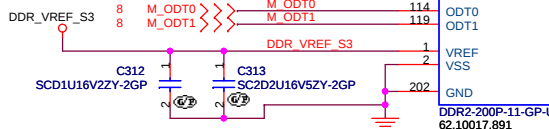
Layout Note:
Place one cap close to every 2 pullup
resistors terminated to +0.9VS



change to 8P4R

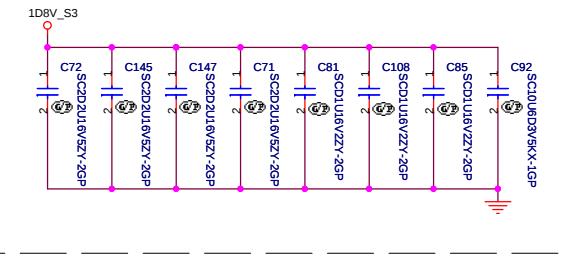


Layout Note:
Place these resistors
closely DM1, all
trace length Max=1.5"

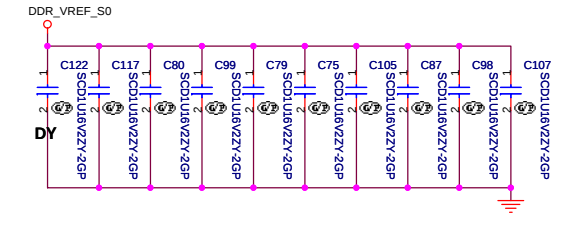


		DM2	
DDR A MA0	102	A0	
DDR A MA1	101	A1	
DDR A MA2	100	A2	
DDR A MA3	99	A3	
DDR A MA4	98	A4	
DDR A MA5	97	A5	
DDR A MA6	96	A6	
DDR A MA7	95	A7	
DDR A MA8	94	A8	
DDR A MA9	93	A9	
DDR A MA10	105	A10/AP	
DDR A MA11	90	A11	
DDR A MA12	89	A12	
DDR A MA13	116	A13	
DDR A MA14	86	A14	
DDR A BS2	85	A15	
		BA16/BA	
DDR A BS0	107	BA0	
DDR A BS1	106	BA1	
DDR A D0	5	DQ0	
DDR A D1	7	DQ1	
DDR A D2	17	DQ2	
DDR A D3	19	DQ3	
DDR A D4	4	DQ4	
DDR A D5	6	DQ5	
DDR A D6	14	DQ6	
DDR A D7	16	DQ7	
DDR A D8	23	DQ8	
DDR A D9	25	DQ9	
DDR A D10	35	DQ10	
DDR A D11	37	DQ11	
DDR A D12	20	DQ12	
DDR A D13	22	DQ13	
DDR A D14	36	DQ14	
DDR A D15	38	DQ15	
DDR A D16	43	DQ16	
DDR A D17	45	DQ17	
DDR A D18	55	DQ18	
DDR A D19	57	DQ19	
DDR A D20	44	DQ20	
DDR A D21	46	DQ21	
DDR A D22	56	DQ22	
DDR A D23	58	DQ23	
DDR A D24	61	DQ24	
DDR A D25	63	DQ25	
DDR A D26	73	DQ26	
DDR A D27	75	DQ27	
DDR A D28	62	DQ28	
DDR A D29	64	DQ29	
DDR A D30	74	DQ30	
DDR A D31	76	DQ31	
DDR A D32	123	DQ32	
DDR A D33	125	DQ33	
DDR A D34	135	DQ34	
DDR A D35	137	DQ35	
DDR A D36	124	DQ36	
DDR A D37	126	DQ37	
DDR A D38	134	DQ38	
DDR A D39	136	DQ39	
DDR A D40	141	DQ40	
DDR A D41	143	DQ41	
DDR A D42	151	DQ42	
DDR A D43	153	DQ43	
DDR A D44	140	DQ44	
DDR A D45	142	DQ45	
DDR A D46	152	DQ46	
DDR A D47	154	DQ47	
DDR A D48	157	DQ48	
DDR A D49	159	DQ49	
DDR A D50	173	DQ50	
DDR A D51	175	DQ51	
DDR A D52	158	DQ52	
DDR A D53	160	DQ53	
DDR A D54	174	DQ54	
DDR A D55	176	DQ55	
DDR A D56	179	DQ56	
DDR A D57	181	DQ57	
DDR A D58	189	DQ58	
DDR A D59	189	DQ59	
DDR A D60	180	DQ60	
DDR A D61	182	DQ61	
DDR A D62	192	DQ62	
DDR A D63	194	DQ63	
DDR A DQS#0	11	/DQS0	
DDR A DQS#1	29	/DQS1	
DDR A DQS#2	49	/DQS2	
DDR A DQS#3	68	/DQS3	
DDR A DQS#4	129	/DQS4	
DDR A DQS#5	146	/DQS5	
DDR A DQS#6	167	/DQS6	
DDR A DQS#7	186	/DQS7	
DDR A DQS0	13	DQS0	
DDR A DQS1	31	DQS1	
DDR A DQS2	51	DQS2	
DDR A DQS3	70	DQS3	
DDR A DQS4	131	DQS4	
DDR A DQS5	148	DQS5	
DDR A DQS6	169	DQS6	
DDR A DQS7	188	DQS7	

Layout Note:
Place near DM2

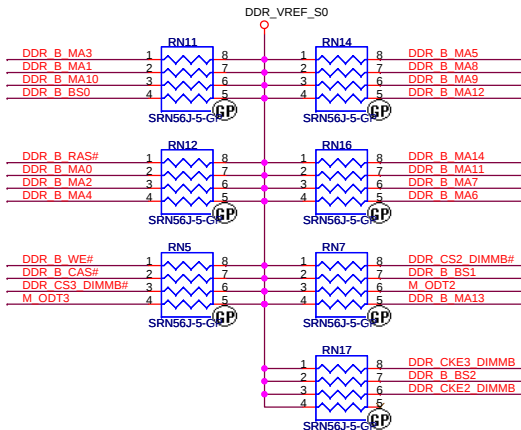


Layout Note:
Place one cap close to every 2 pullup resistors terminated to +0.9VS



9 DDR_B_DQS#[0..7] <<>>
9 DDR_B_D[0..63] <<>>
9 DDR_B_DM[0..7] >>>
9 DDR_B_DQS[0..7] <<>>
9 DDR_B_MA[0..14] >>>
9 DDR_B_BS[0..2] >>>

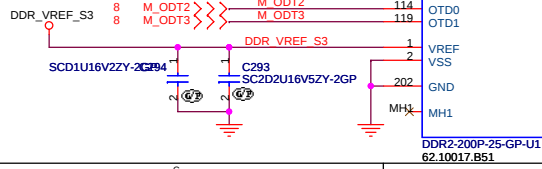
Layout Note:
Place these resistors closely DM2,all trace length Max=1.5"



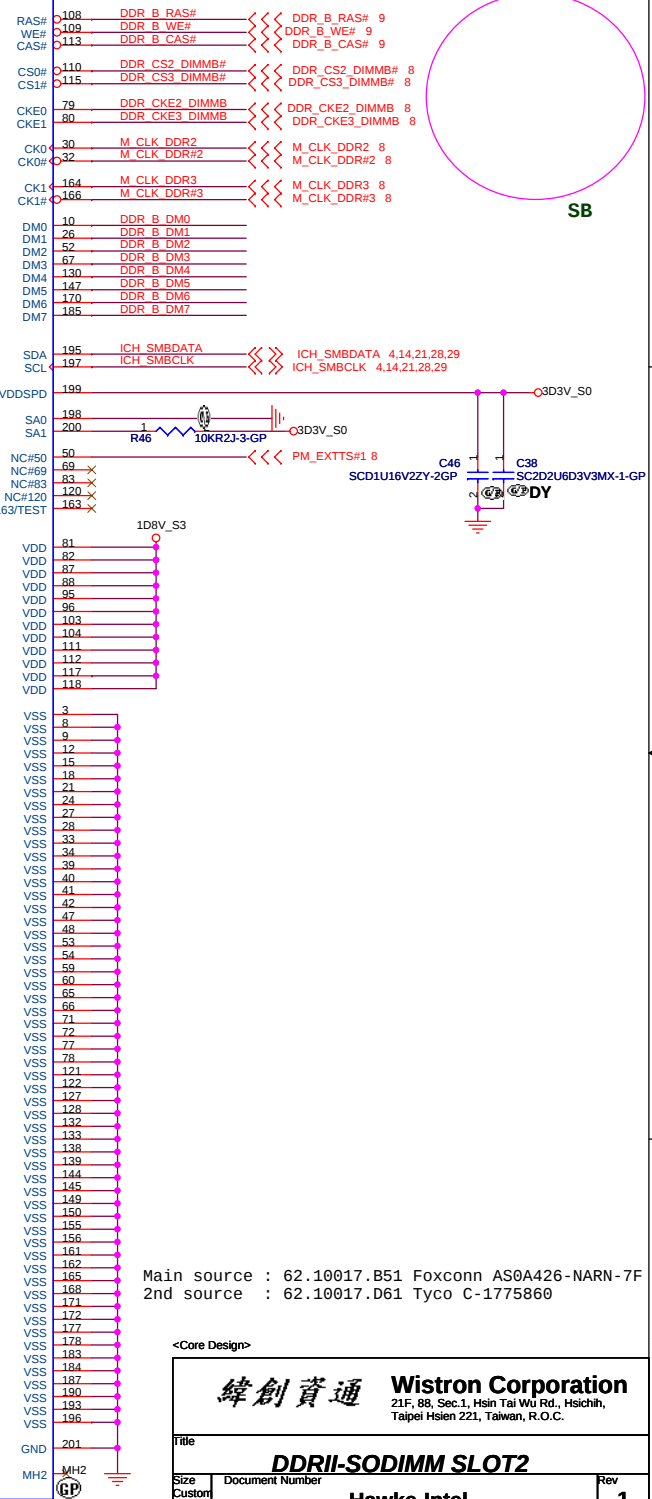
DDR_B_MA0 102
DDR_B_MA1 101
DDR_B_MA2 100
DDR_B_MA3 99
DDR_B_MA4 98
DDR_B_MA5 97
DDR_B_MA6 96
DDR_B_MA7 95
DDR_B_MA8 94
DDR_B_MA9 93
DDR_B_MA10 92
DDR_B_MA11 91
DDR_B_MA12 90
DDR_B_MA13 89
DDR_B_MA14 88
DDR_B_BS2 87
DDR_B_BS1 86
A0
A1
A2
A3
A4
A5
A6
A7
A8
A9
A10/AP
A11
A12
A13
A14
A15
A16/BA2

DDR_B_D0 5
DDR_B_D1 7
DDR_B_D2 17
DDR_B_D3 19
DDR_B_D4 18
DDR_B_D5 6
DDR_B_D6 14
DDR_B_D7 16
DDR_B_D8 23
DDR_B_D9 25
DDR_B_D10 35
DDR_B_D11 37
DDR_B_D12 20
DDR_B_D13 22
DDR_B_D14 38
DDR_B_D15 38
DDR_B_D16 43
DDR_B_D17 45
DDR_B_D18 55
DDR_B_D19 57
DDR_B_D20 44
DDR_B_D21 46
DDR_B_D22 56
DDR_B_D23 58
DDR_B_D24 61
DDR_B_D25 63
DDR_B_D26 73
DDR_B_D27 75
DDR_B_D28 62
DDR_B_D29 64
DDR_B_D30 74
DDR_B_D31 76
DDR_B_D32 123
DDR_B_D33 125
DDR_B_D34 135
DDR_B_D35 137
DDR_B_D36 124
DDR_B_D37 126
DDR_B_D38 134
DDR_B_D39 136
DDR_B_D40 141
DDR_B_D41 143
DDR_B_D42 151
DDR_B_D43 153
DDR_B_D44 140
DDR_B_D45 142
DDR_B_D46 152
DDR_B_D47 154
DDR_B_D48 157
DDR_B_D49 159
DDR_B_D50 173
DDR_B_D51 175
DDR_B_D52 158
DDR_B_D53 160
DDR_B_D54 174
DDR_B_D55 176
DDR_B_D56 179
DDR_B_D57 181
DDR_B_D58 189
DDR_B_D59 191
DDR_B_D60 180
DDR_B_D61 182
DDR_B_D62 192
DDR_B_D63 194
DQ0
DQ1
DQ2
DQ3
DQ4
DQ5
DQ6
DQ7
DQ8
DQ9
DQ10
DQ11
DQ12
DQ13
DQ14
DQ15
DQ16
DQ17
DQ18
DQ19
DQ20
DQ21
DQ22
DQ23
DQ24
DQ25
DQ26
DQ27
DQ28
DQ29
DQ30
DQ31
DQ32
DQ33
DQ34
DQ35
DQ36
DQ37
DQ38
DQ39
DQ40
DQ41
DQ42
DQ43
DQ44
DQ45
DQ46
DQ47
DQ48
DQ49
DQ50
DQ51
DQ52
DQ53
DQ54
DQ55
DQ56
DQ57
DQ60
DQ61
DQ62
DQ63

DDR_B_DQS#0 11
DDR_B_DQS#1 25
DDR_B_DQS#2 68
DDR_B_DQS#3 129
DDR_B_DQS#4 146
DDR_B_DQS#5 167
DDR_B_DQS#6 186
DDR_B_DQS#7 186
DQS0#
DQS1#
DQS2#
DQS3#
DQS4#
DQS5#
DQS6#
DQS7#
DQS0
DQS1
DQS2
DQS3
DQS4
DQS5
DQS6
DQS7



REVERSE TYPE High 9.2 mm



Main source : 62.10017.B51 Foxconn AS0A426-NARN-7F
2nd source : 62.10017.D61 Tyco C-1775860

<Core Design>

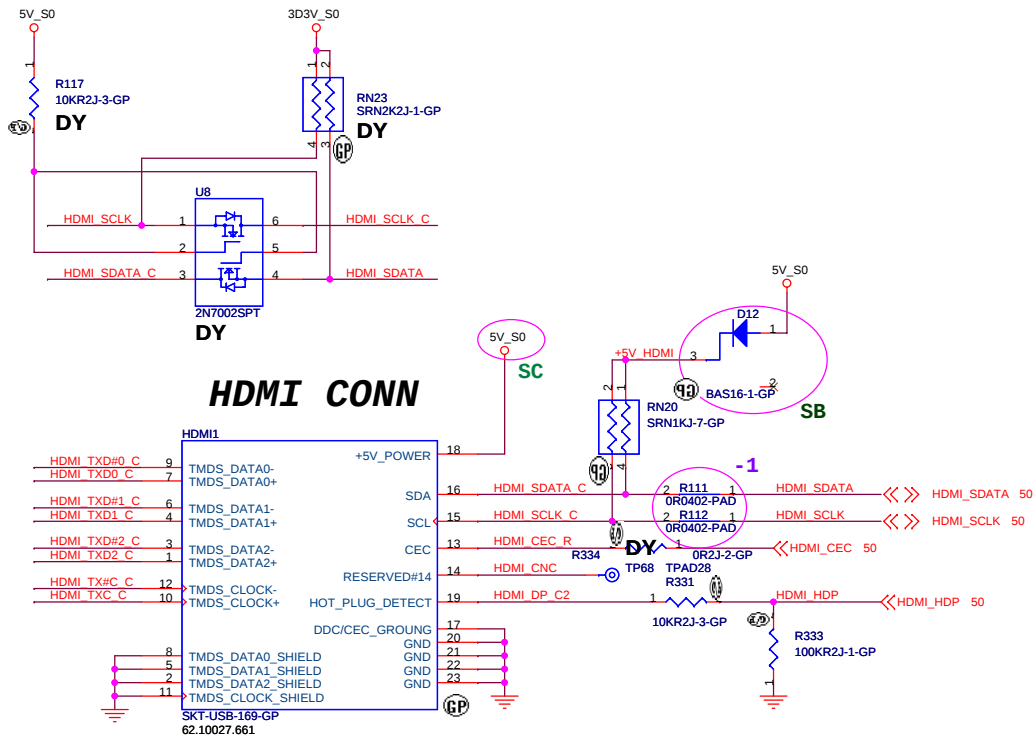
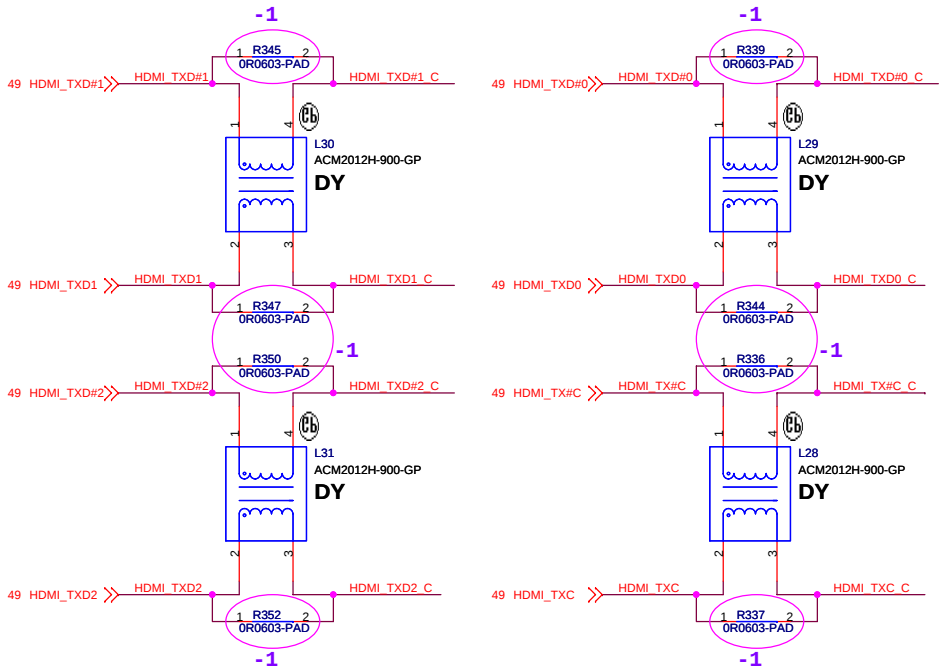
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **DDRII-SODIMM SLOT2**

Size: Custom Document Number: **Hawke-Intel** Rev: **-1**

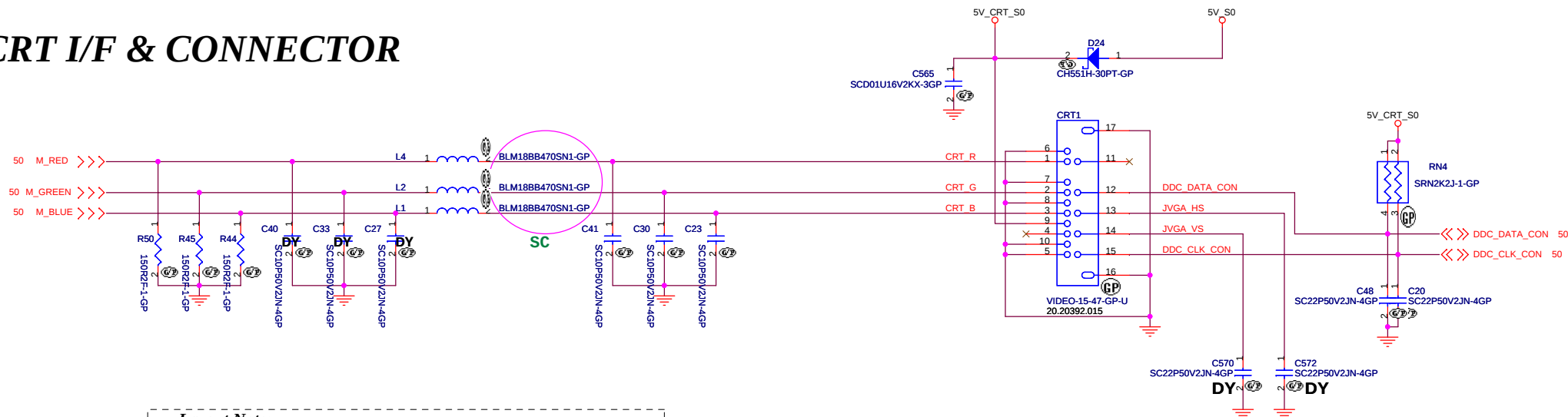
Date: Sunday, September 09, 2007 Sheet 15 of 57

HDMI I/F & CONNECTOR



Main source : 62.10027.661 Molex 47408-0201
2nd source : 62.10078.121 Tyco C1759548-1

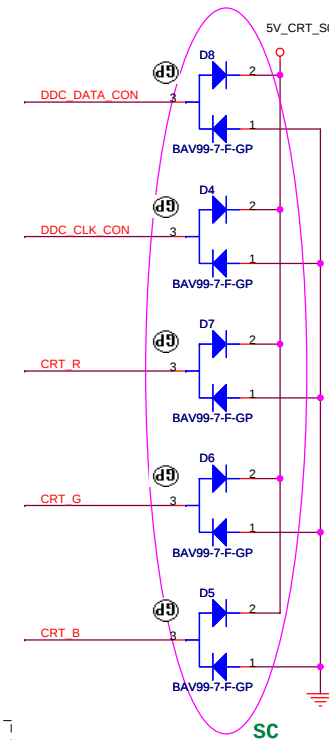
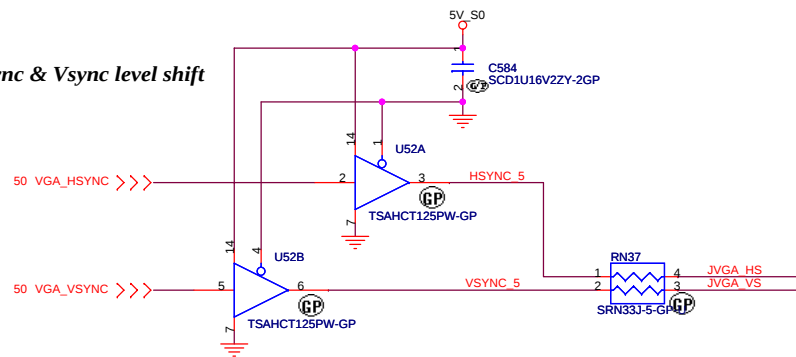
CRT I/F & CONNECTOR



Layout Note:

Pi-filter & 150 Ohm pull-down resistors should be as close as to CRT CONN. RGB will hit 75 Ohm first, pi-filter, then CRT CONN.

Hsync & Vsync level shift



TP28-75-GP	TP177	1	5V_CRT_S0
TP28-75-GP	TP176	1	DDC_DATA_CON
TP28-75-GP	TP179	1	DDC_CLK_CON
TP28-75-GP	TP178	1	CRT_R
TP28-75-GP	TP180	1	CRT_G
TP28-75-GP	TP182	1	CRT_B
TP28-75-GP	TP181	1	JVGA_HS
TP28-75-GP	TP183	1	JVGA_VS

For AFTE, place them on the some side.

<Core Design>

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

CRT Connector

Size
A3

Document Number

Hawke-Intel

Rev

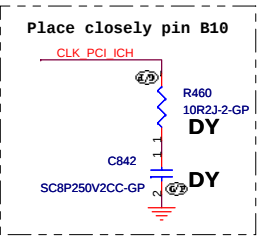
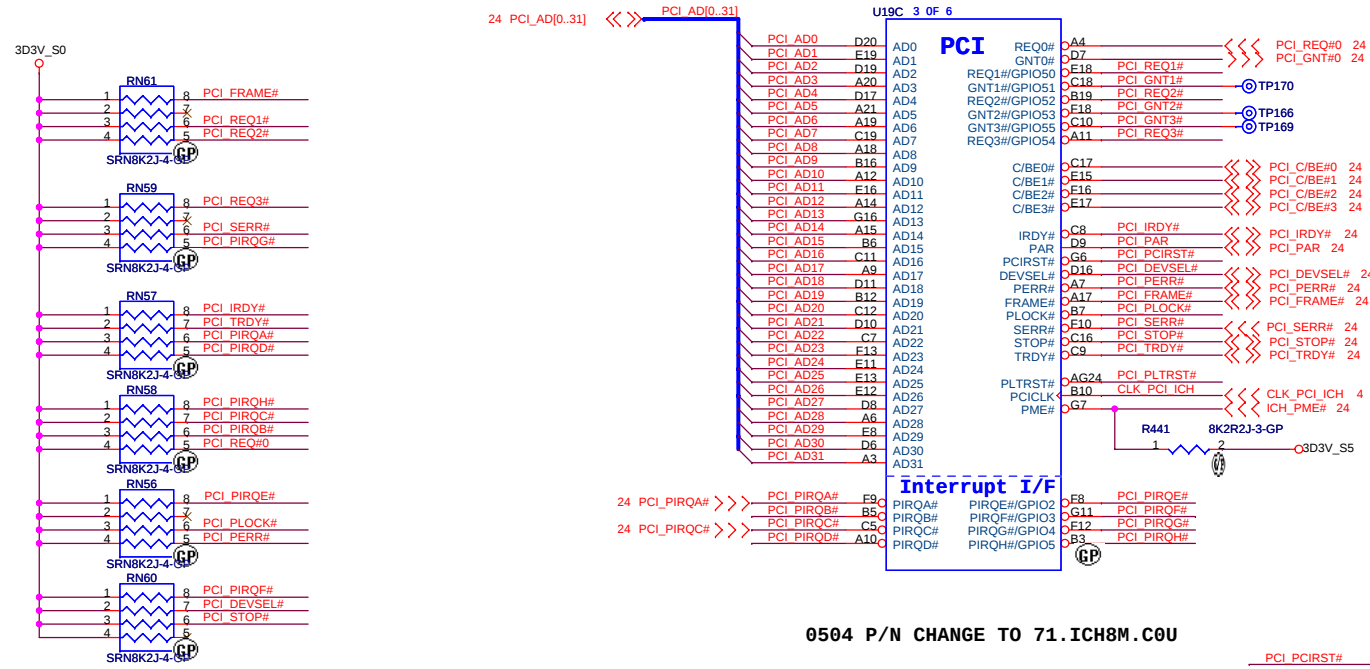
-1

Date: Sunday, September 09, 2007

Sheet 17 of 57

PCI Interface Routing

	IDSEL	INT	REQ	GNT
1394/ MediaCard	AD25	A D	0	0

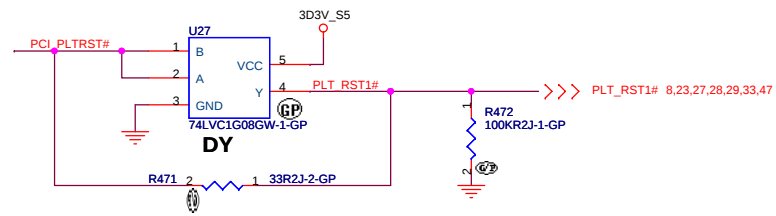
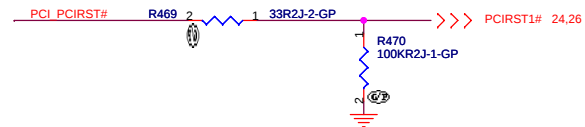
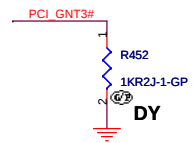


0504 P/N CHANGE TO 71.ICH8M.C0U

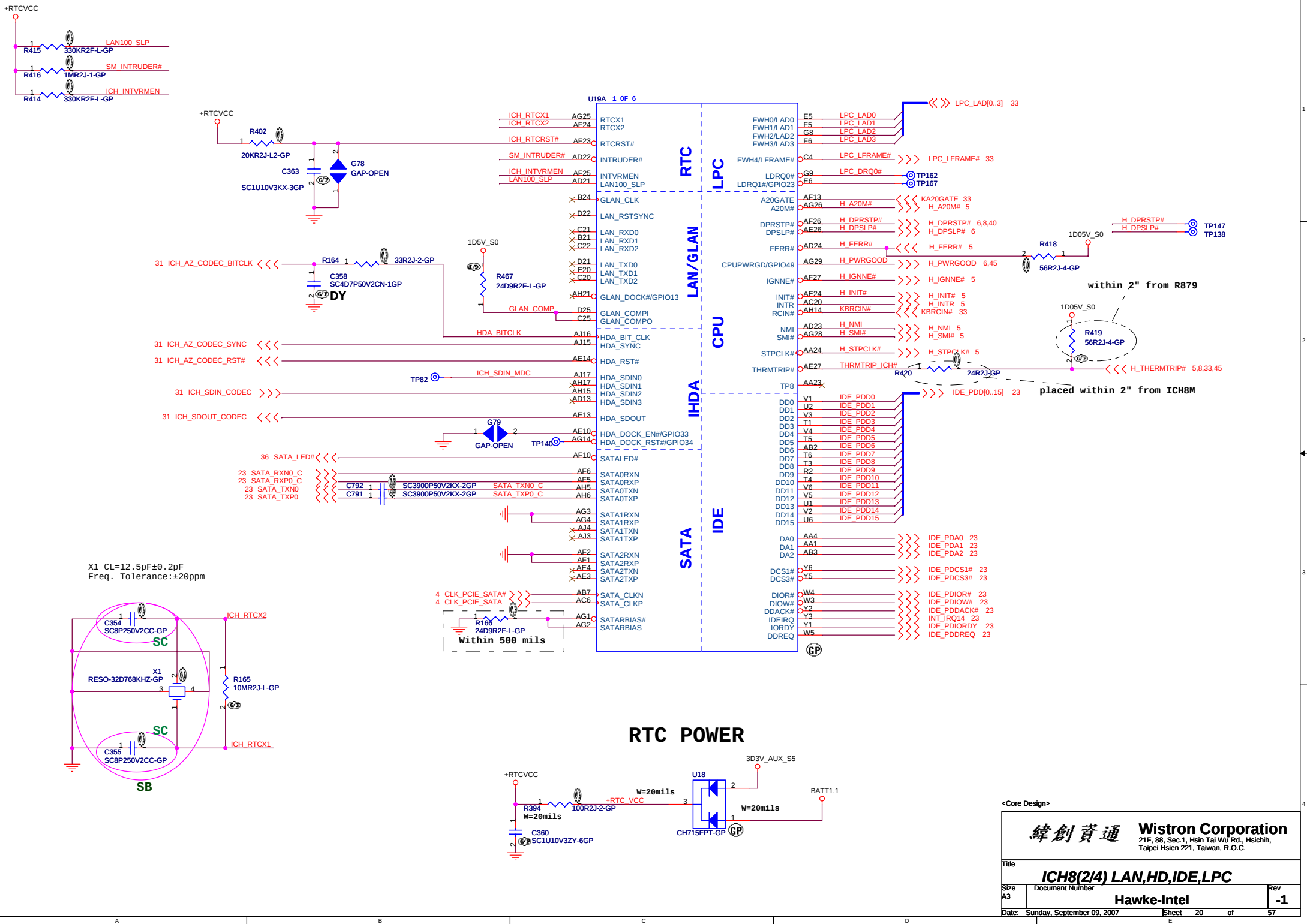
ICH8-Strap PIN

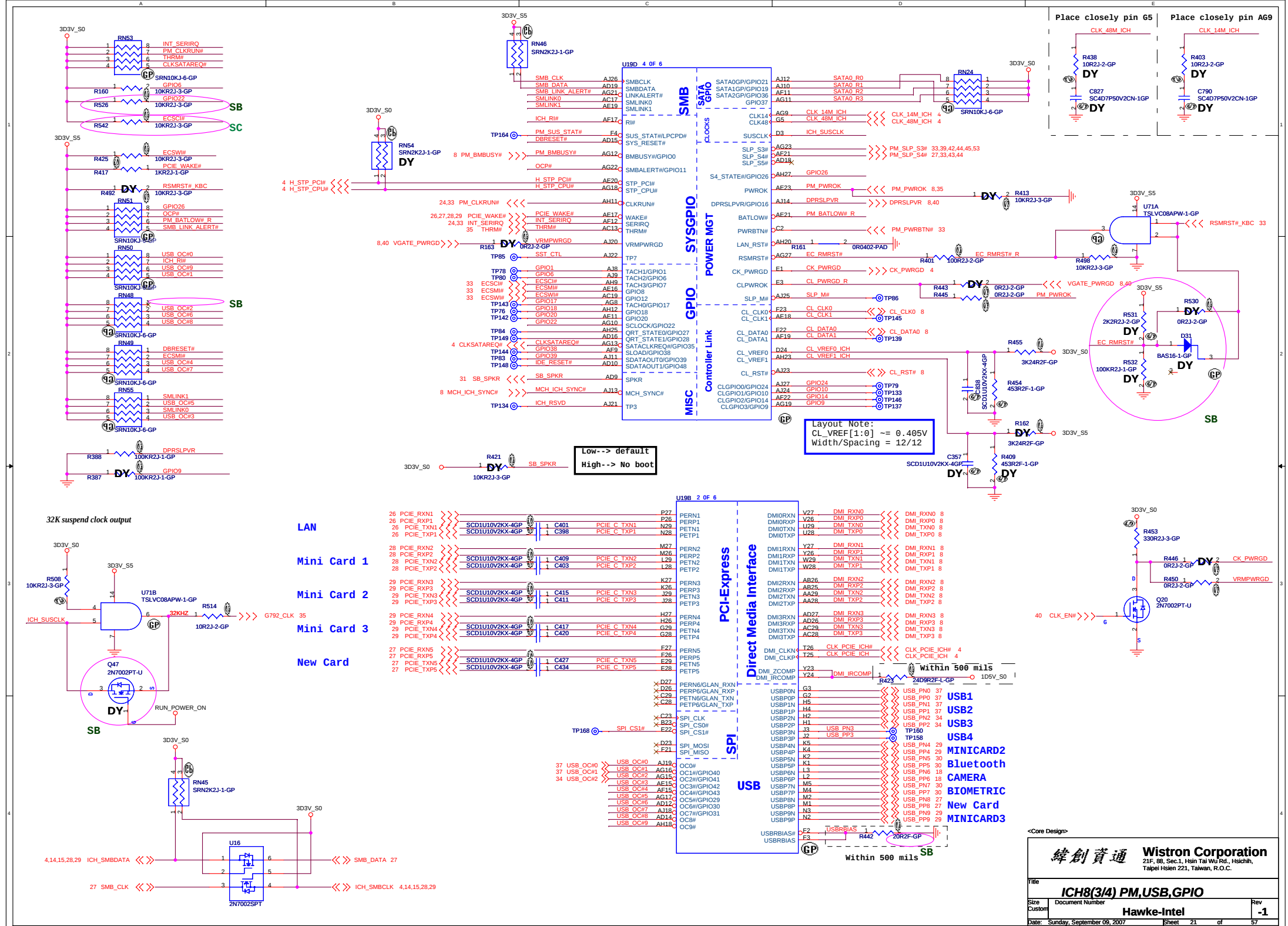
BOOT BIOS Strap		
PCI_GNT#0 (R166)	SPI_CS#1 (R167)	BOOT BIOS Location
0	1	SPI(Default)
1	0	PCI
1	1	LPC
A16 swap override strap		
PCI_GNT#3 (R168)	low = A16 swap override enable high = default	

A16 swap override Strap	
PCI_GNT3#	Low= A16 swap override Enable High= Default *



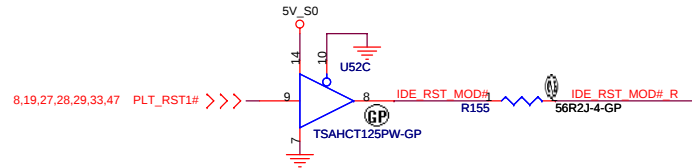
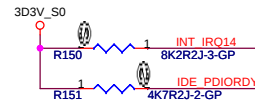
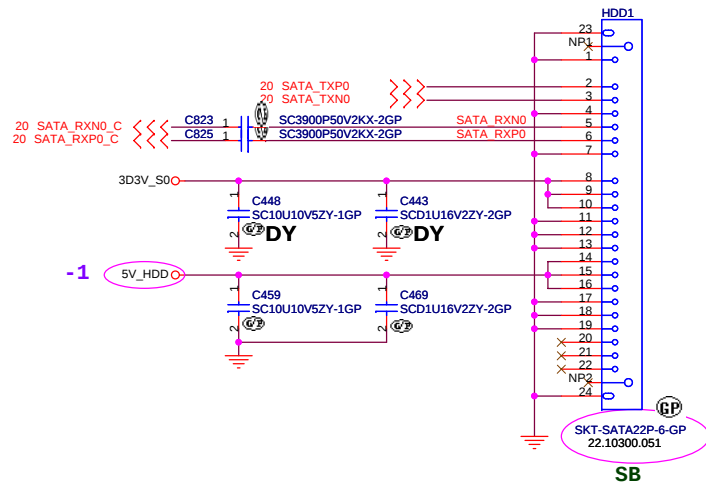
<Core Design>



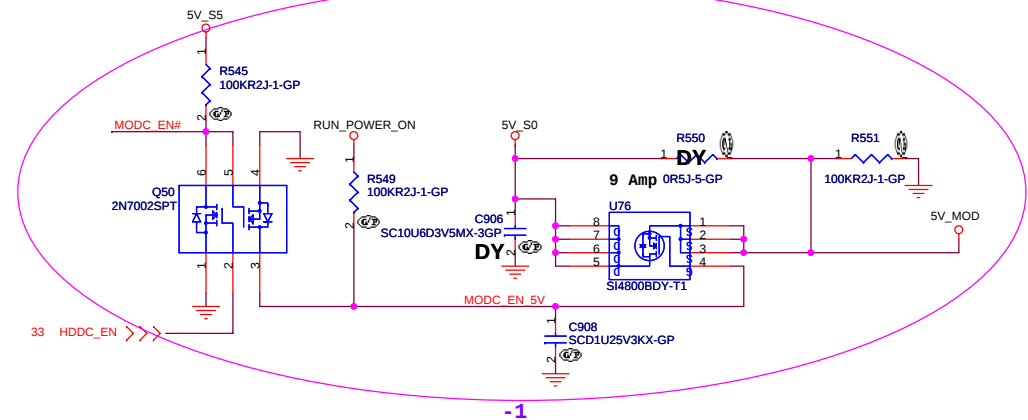
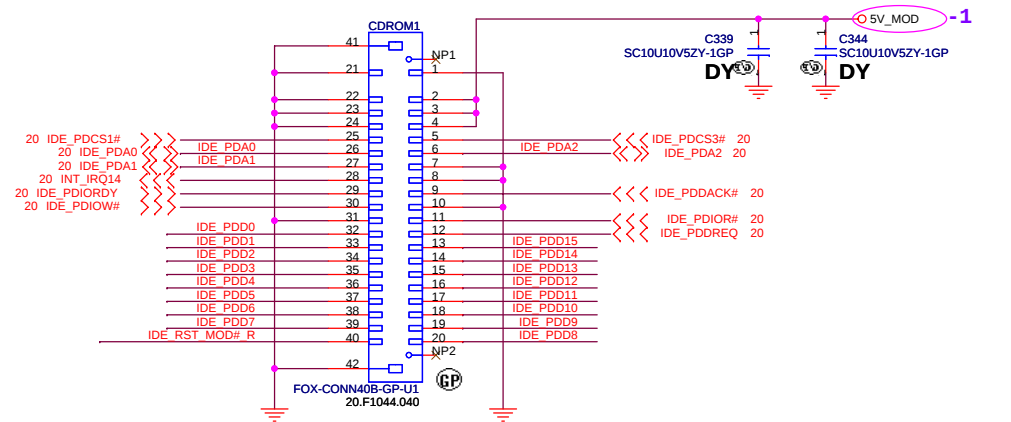




SATA HDD Connector



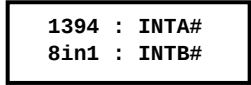
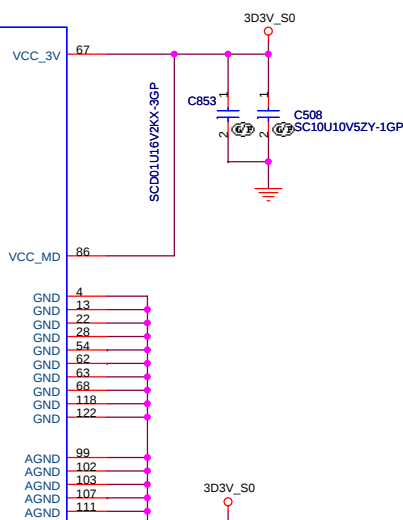
ODD Connector

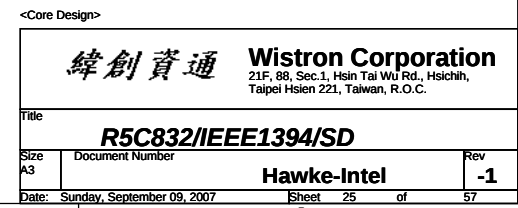


<Core Design>

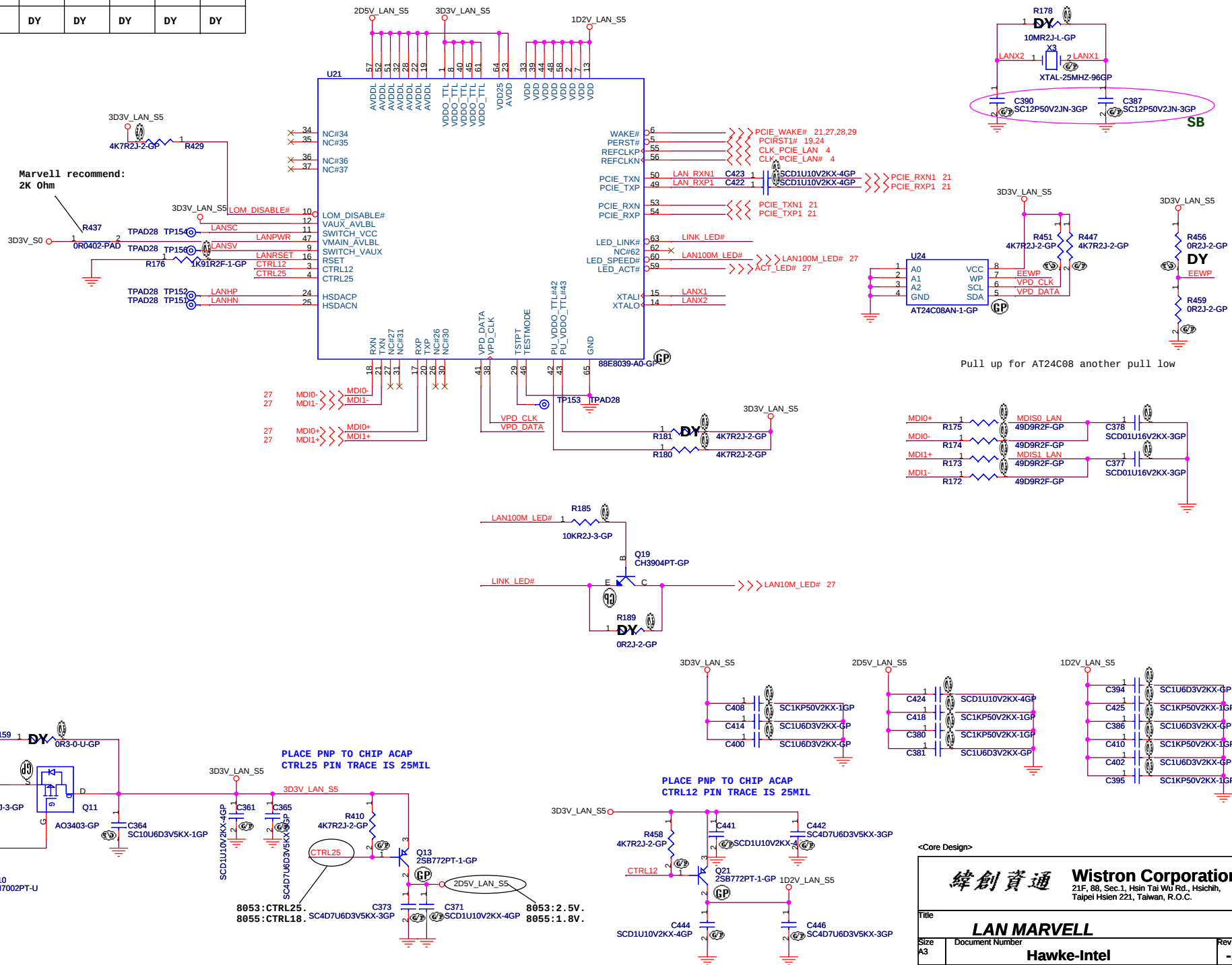
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title		HDD/ODD	
Size A3	Document Number	Hawke-Intel	Rev -1
Date: Sunday, September 09, 2007	Sheet 23 of 57		



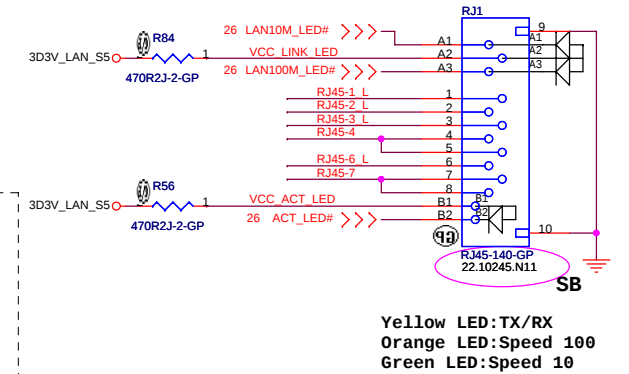
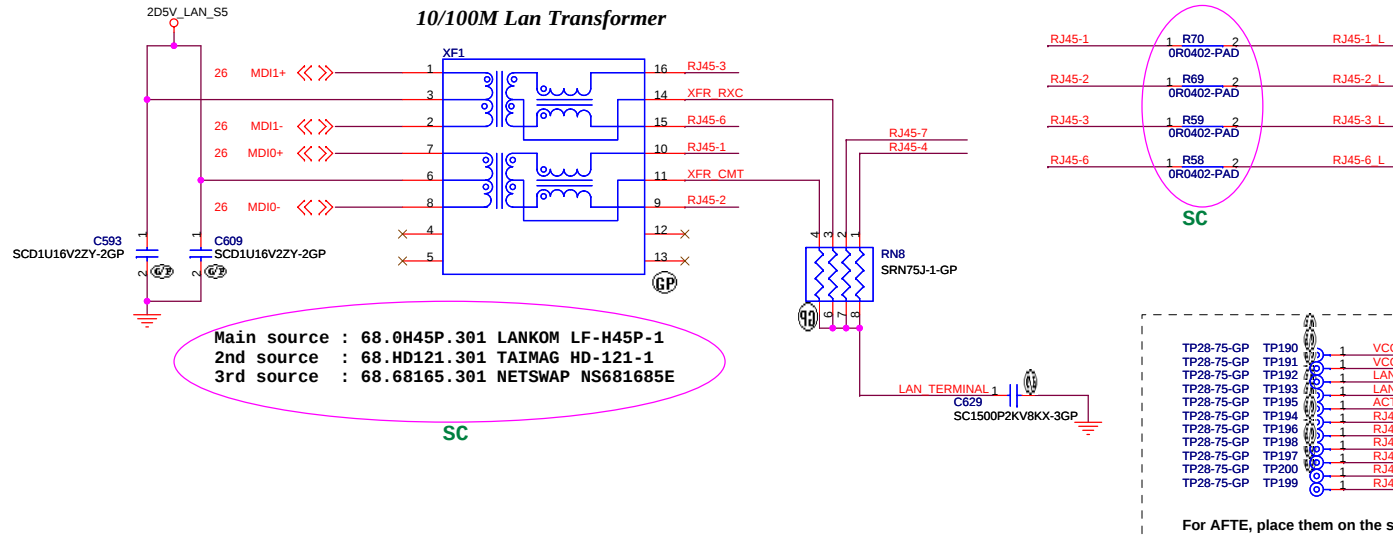


	R181	R176	R172	R173	R174	R175	C377	C378
88E8039	DY	1.91K	49.9	49.9	49.9	49.9	0.01u	0.01u
88E8040	4.7K	2K	DY	DY	DY	DY	DY	DY



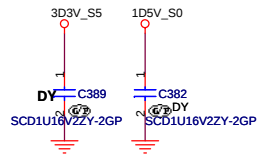
RJ45 Connector

- 1.route on bottom as differential pairs.
- 2.Tx+/Tx- are pairs. Rx+/Rx- are pairs.
- 3.No vias, No 90 degree bends.
- 4.pairs must be equal lengths.
- 5.6mil trace width,12mil separation.
- 6.36mil between pairs and any other trace.
- 7.Must not cross ground moat,except RJ-45 moat.

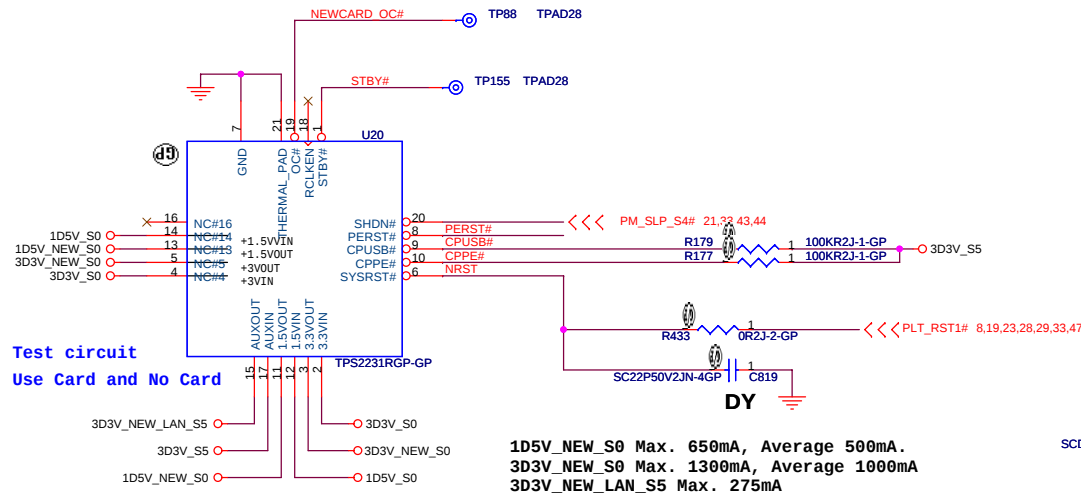
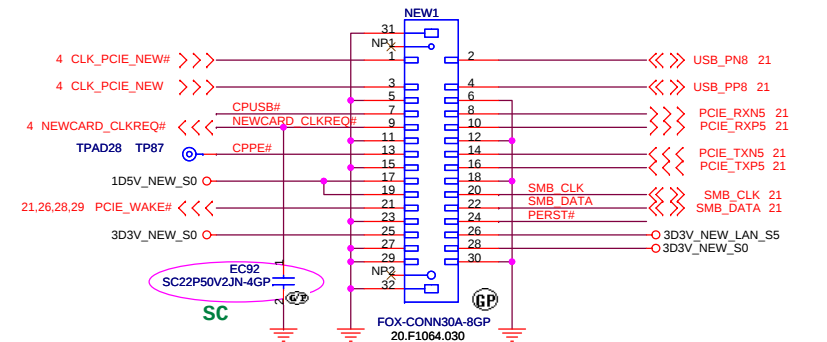
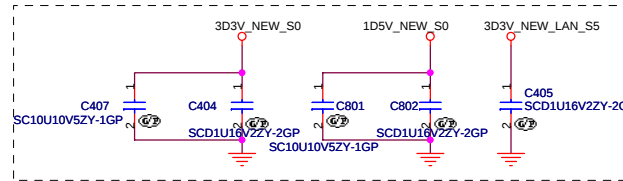


NEWCARD Connector

Place them Near to Chip



Place them Near to Connector

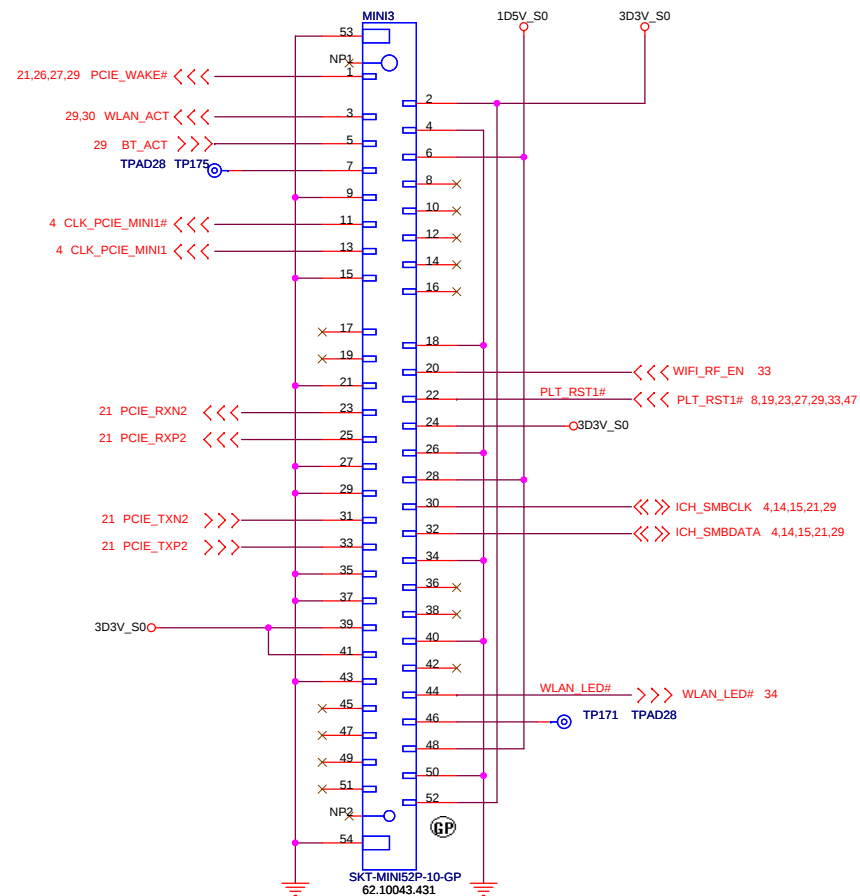


<Core Design>

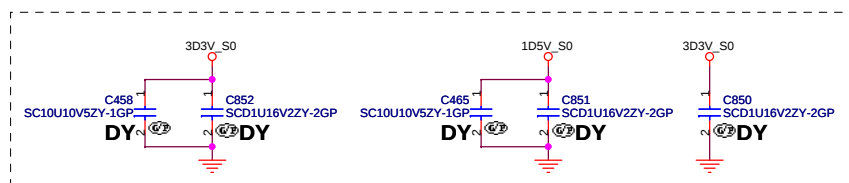
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title		
LAN connector/NEW CARD		
Size	Document Number	Rev
A3	Hawke-Intel	-1
Date: Sunday, September 09, 2007		
Sheet 27 of 57		

Mini Card Connector 1(802.11a/b/g)



Main source : 20.F0992.052 P-Two A54452-A0G16-N
2nd source : 62.10043.551 Tyco 1759553-1

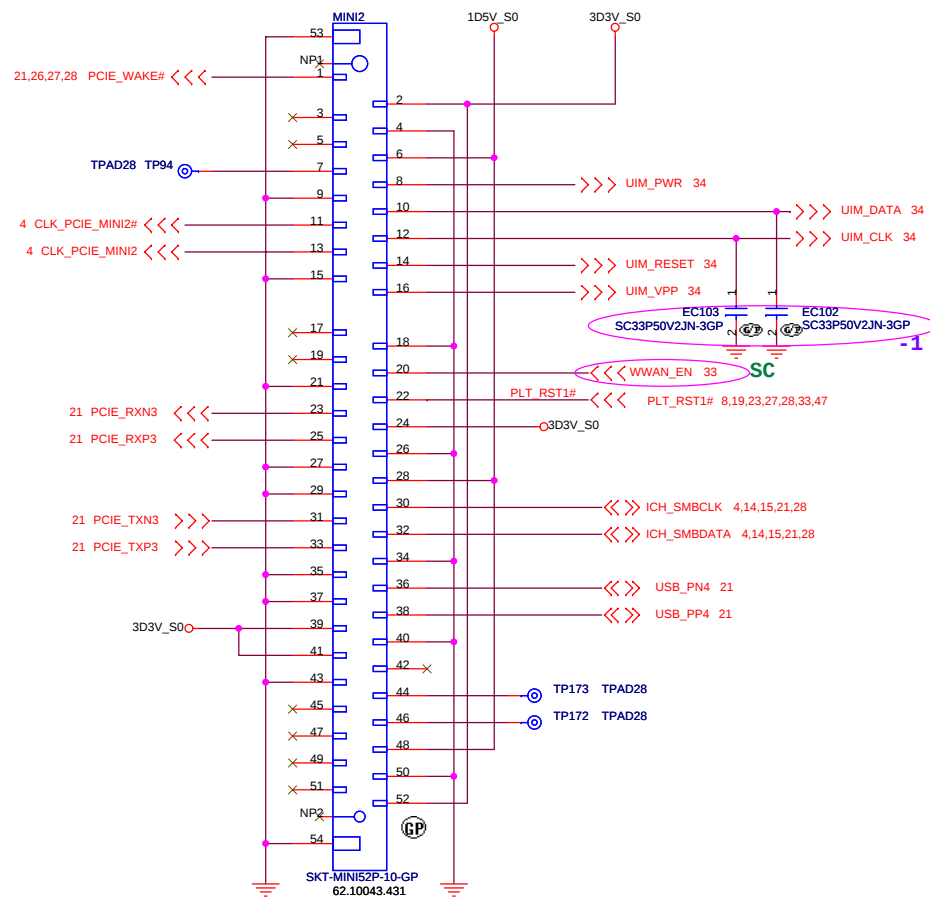


<Core Design>

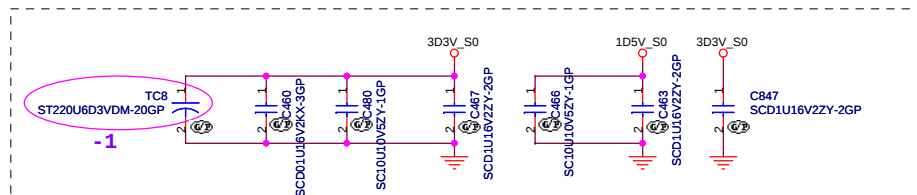
Title		Wistron Corporation	
Size		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
A3		MINI CARD CONN 1	
Date:		Sunday, September 09, 2007	
Sheet		28 of 57	
Document Number		Hawke-Intel	
Rev		-1	

Mini Card Connector

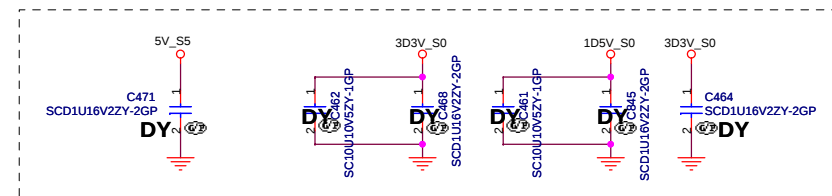
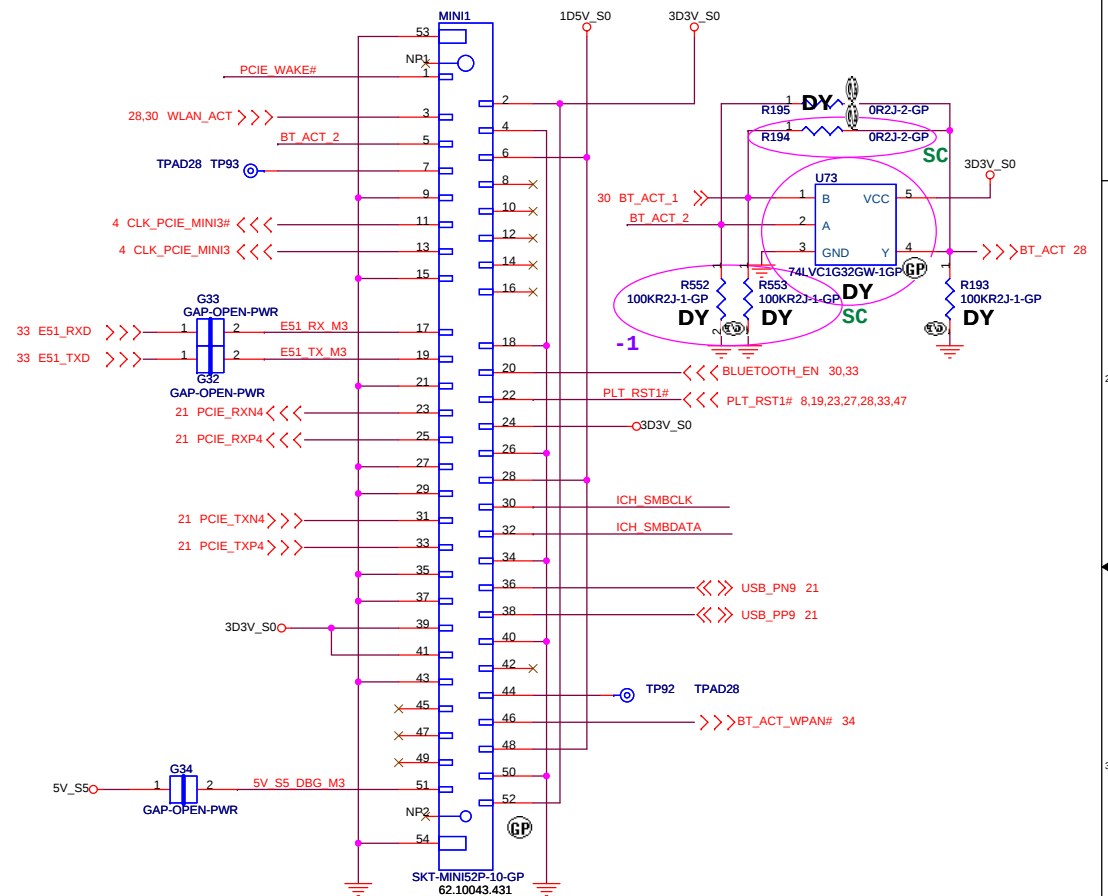
Mini Card Connector 2(WWAN)



Main source : 20.F0992.052 P-Two A54452-A0G16-N
2nd source : 62.10043.551 Tyco 1759553-1



Mini Card Connector 3(Robson/BT)



SPI FLASH ROM

RN43
SRN10KJ-6-GP

SB

16M Bits

EMI REQUEST

Place close to EC

Switch Board

CIR

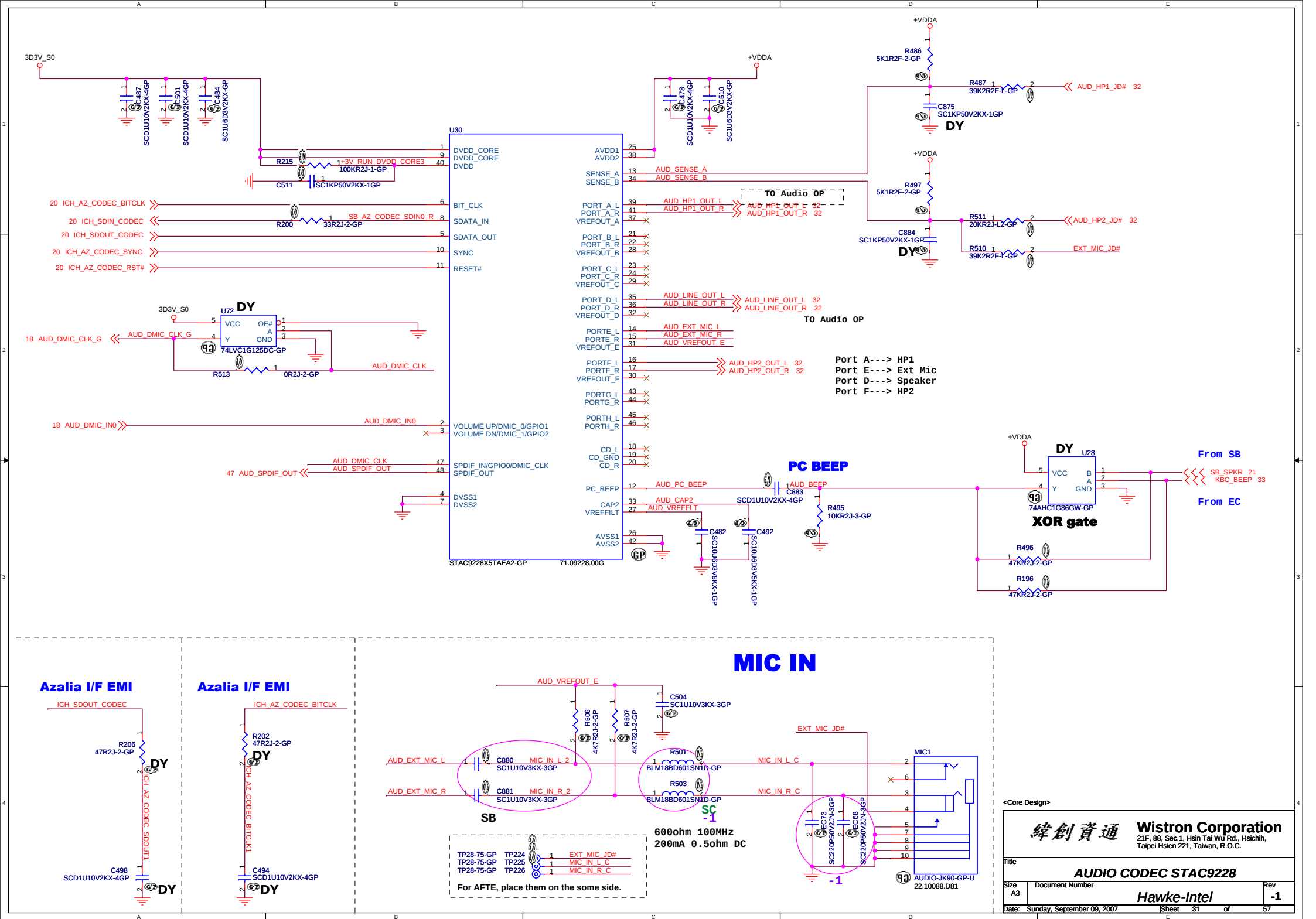
Hall Switch conn.

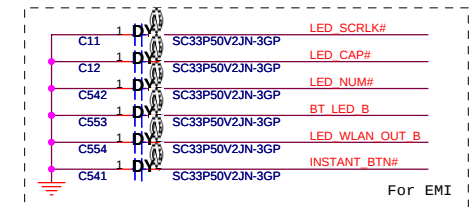
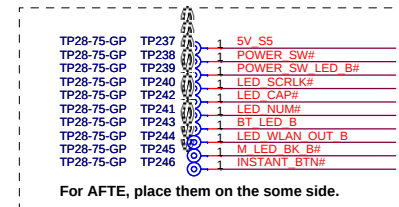
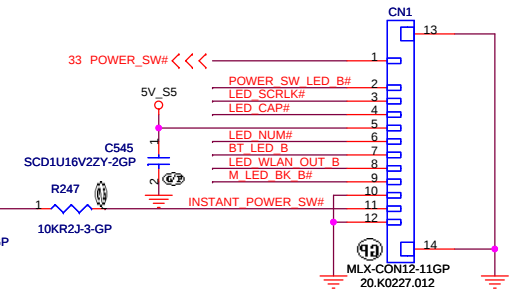
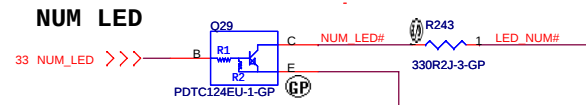
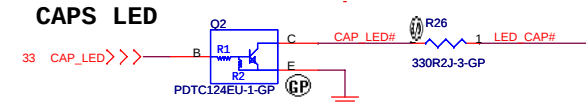
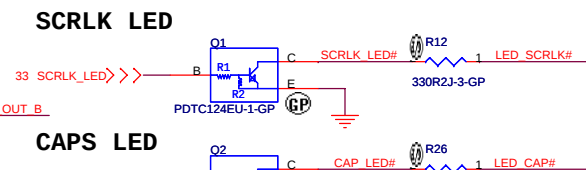
Capacity Button conn.

Bluetooth Module conn.

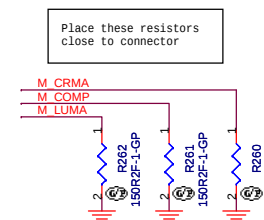
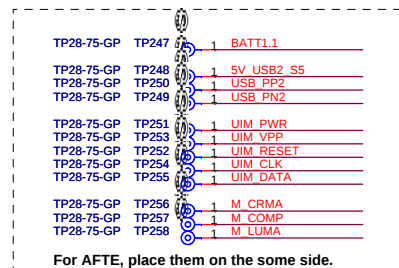
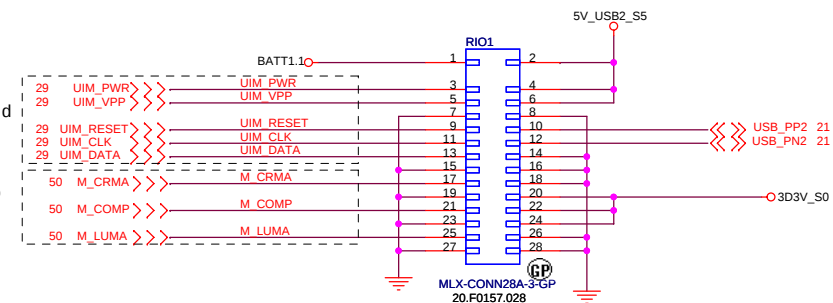
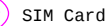
Biometric Conn.

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.



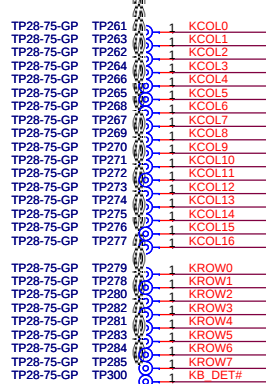
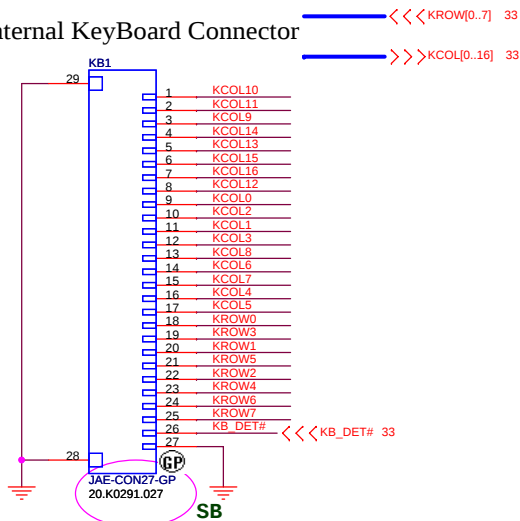


To Right I/O Board



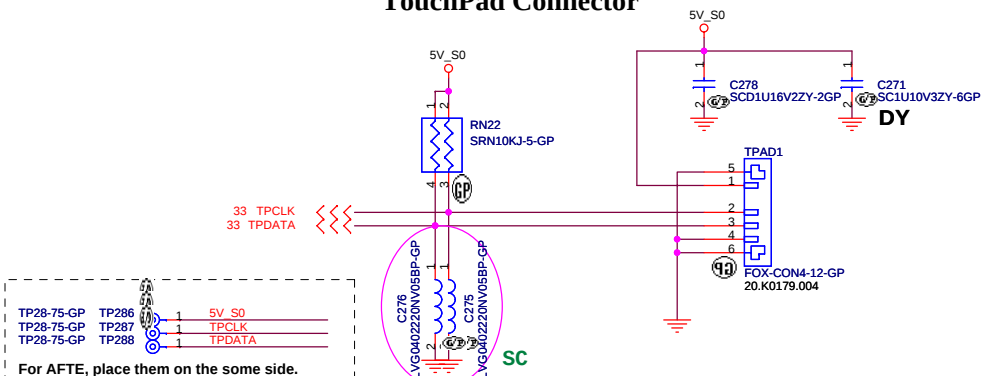
57

Internal KeyBoard Connector



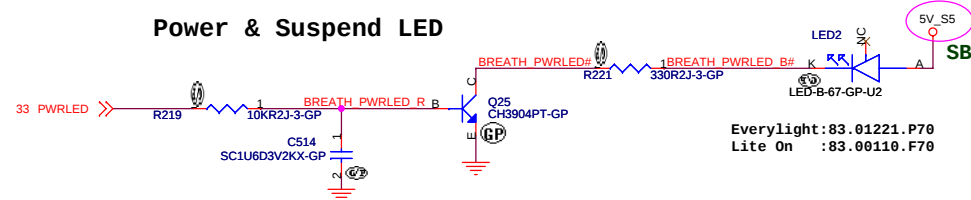
For AFTE, place them on the same side.

TouchPad Connector



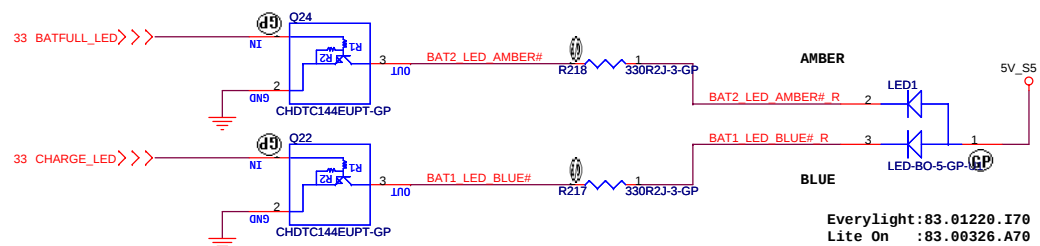
For AFTE, place them on the same side.

Power & Suspend LED



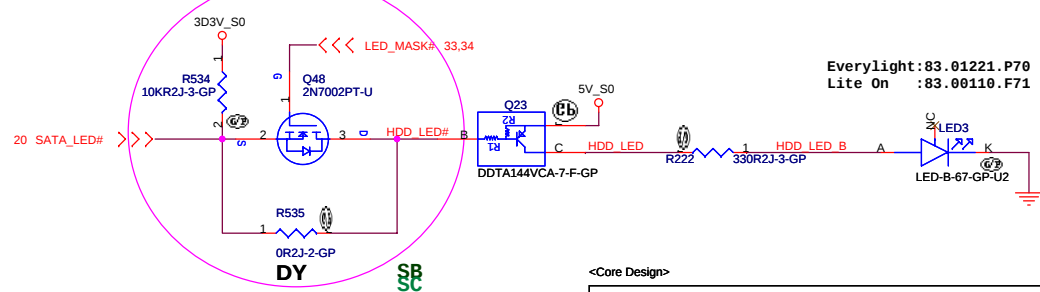
Everylight:83.01221.P70
Lite On :83.00110.F70

Battery LED



Everylight:83.01220.I70
Lite On :83.00326.A70

HDD LED



Everylight:83.01221.P70
Lite On :83.00110.F71

LED Board

LED NAME

ACTIVE SIGNAL

Power Button LED	PWR_BTN_LED	*
Instant Power Button LED	INST_ON_LED	*
WLAN LED	WLAN_LED_TEST (from KBC) WLAN_LED# (from Mini)	
Bluetooth LED	BT_ACT_WPAN# (from Mini) BT_ACT_K# (from BT)	
NUM LED	NUM_LED (from KBC)	
SCRLK LED	SCRLK_LED (from KBC)	
CAPS LED	CAP_LED (from KBC)	

Main Board

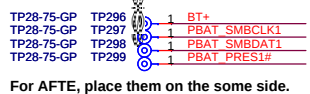
Power & Suspend LED	PWRLED (from KBC)
HDD LED	SATA_LED# (from ICH)
Battery LED	BATFULL_LED (from KBC) CHARGE_LED

<Core Design>

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title	KeyBoard/Touchpad	Rev
Size	Document Number	
A3	Hawke-Intel	-1
Date: Sunday, September 09, 2007	Sheet 36	of 57

**To Left I/O Board
(Adapter In/ USB x 2)**



緯創資通 **Wistron Corporation**
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

AD/BATT CONN

Size	A3
------	----

Document Number

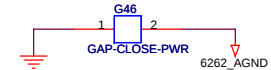
Hawke-Intel

Rev	
1	

Date: Sunday, September 09, 2007

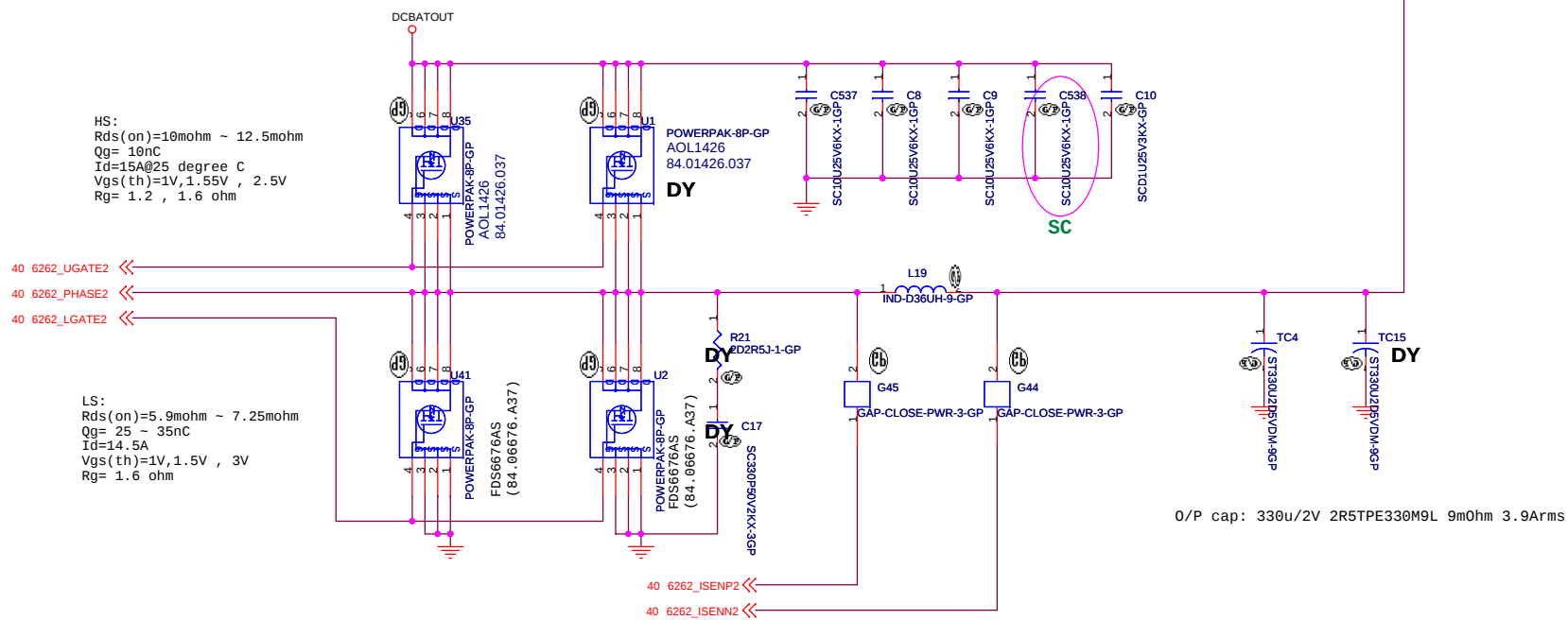
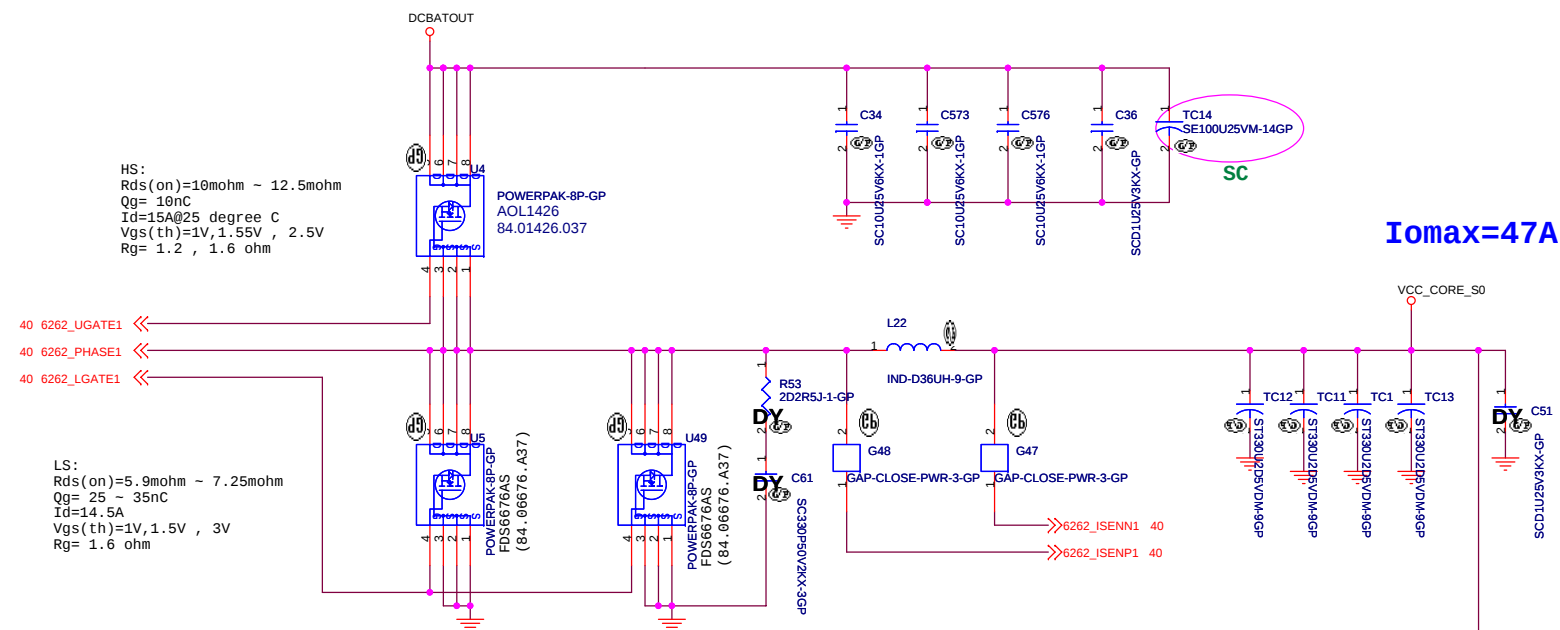
Sheet 37 of 57



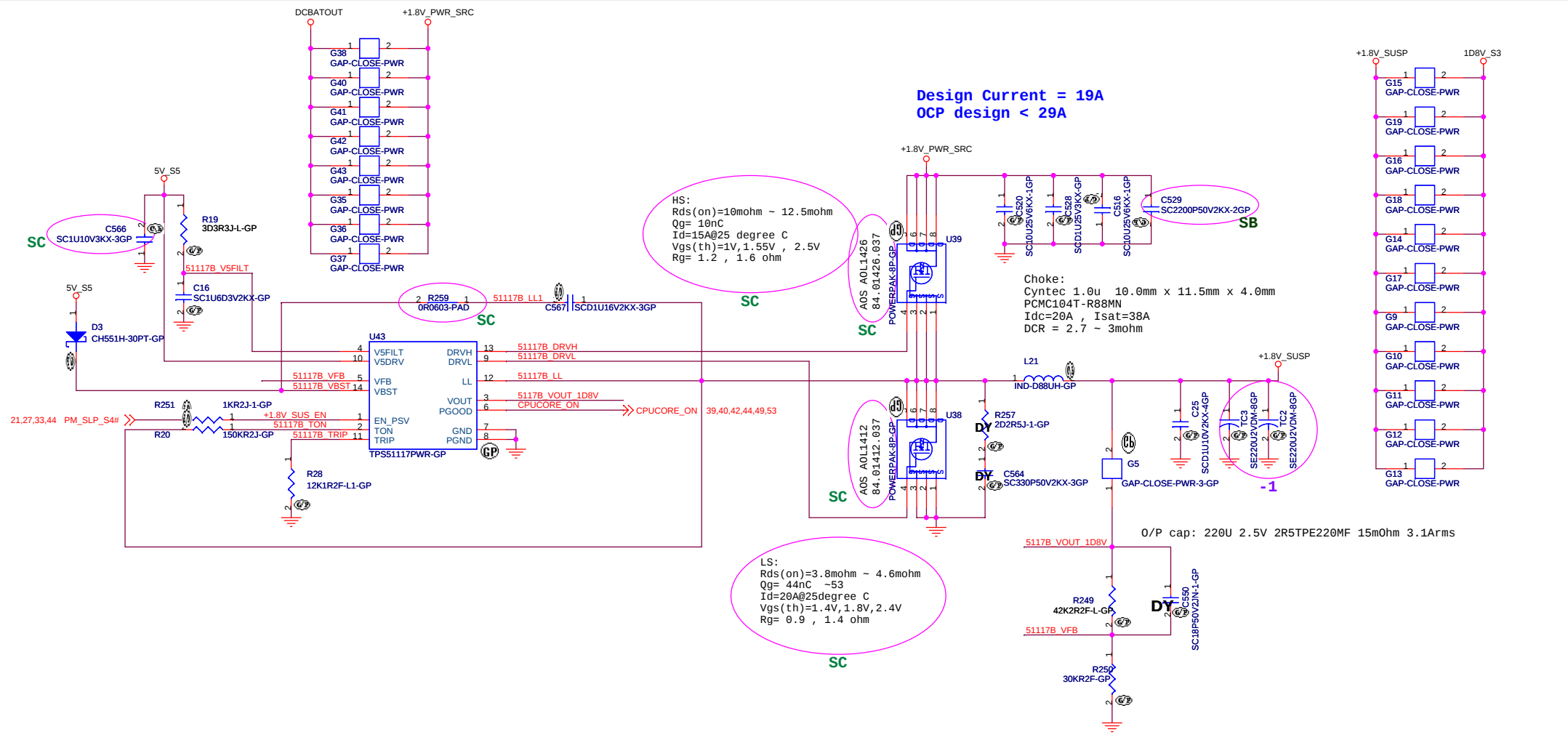


緯創資通 **Wistron Corporation**
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

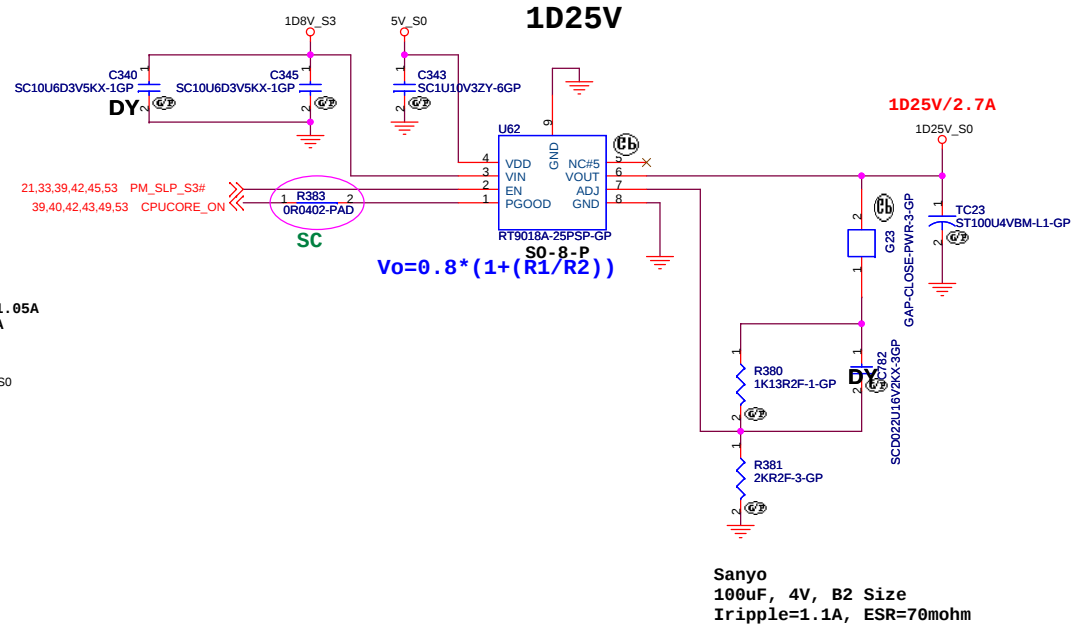
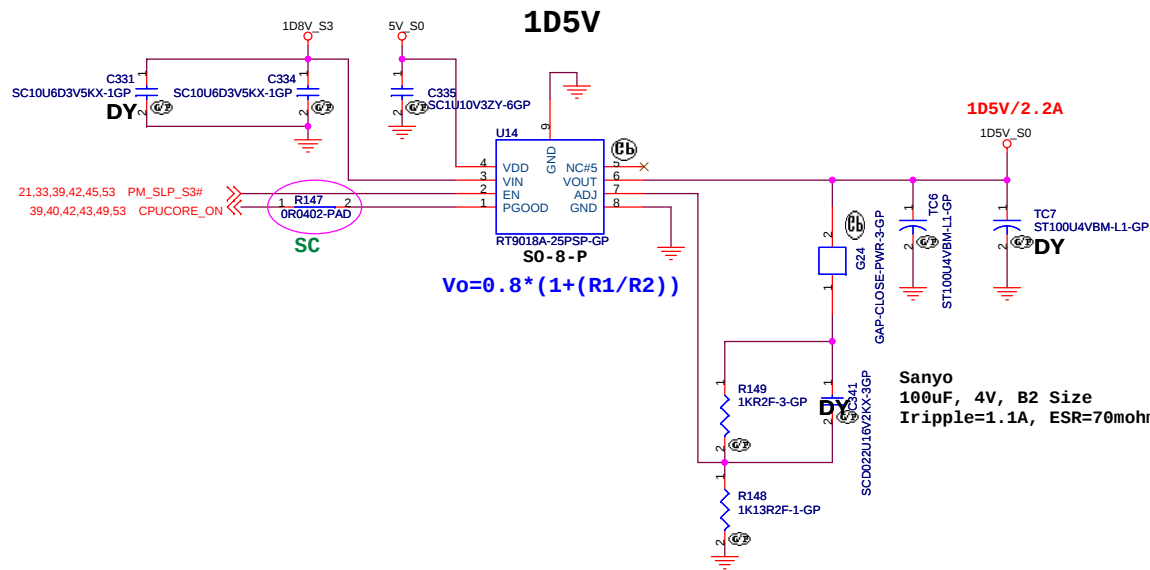
57



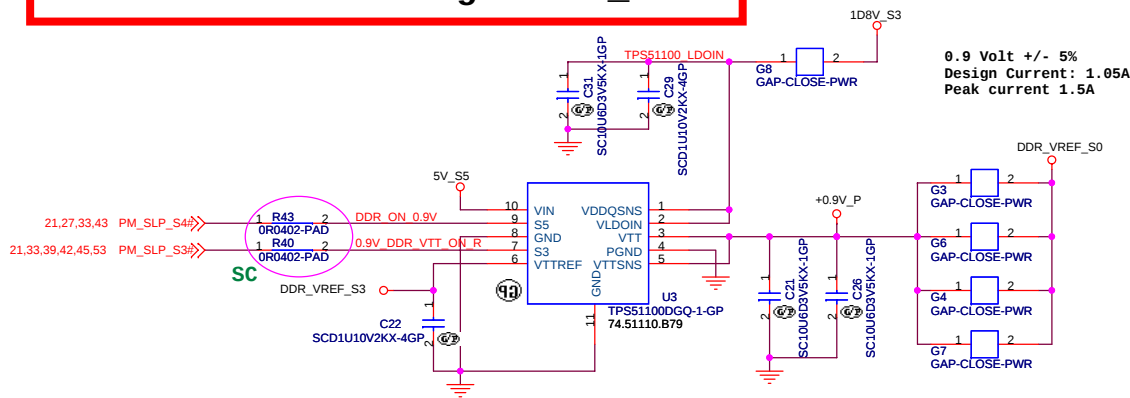
If VCC_SENSE and VSS_SENSE pins have pulled resistors to VCC_CORE_S0
==> Remove R44/R45/R46/R47.



$V_{out} = 0.75V * (R1 + R2) / R2$

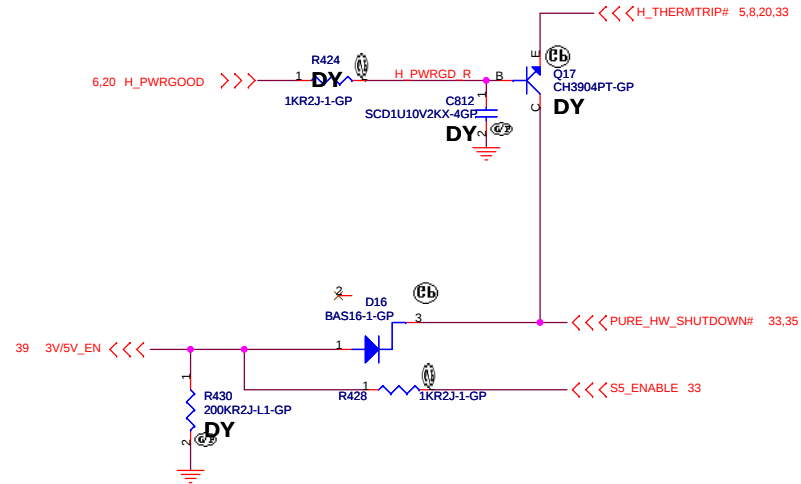


SSID = PWR.Plane.Regulator_0.9V

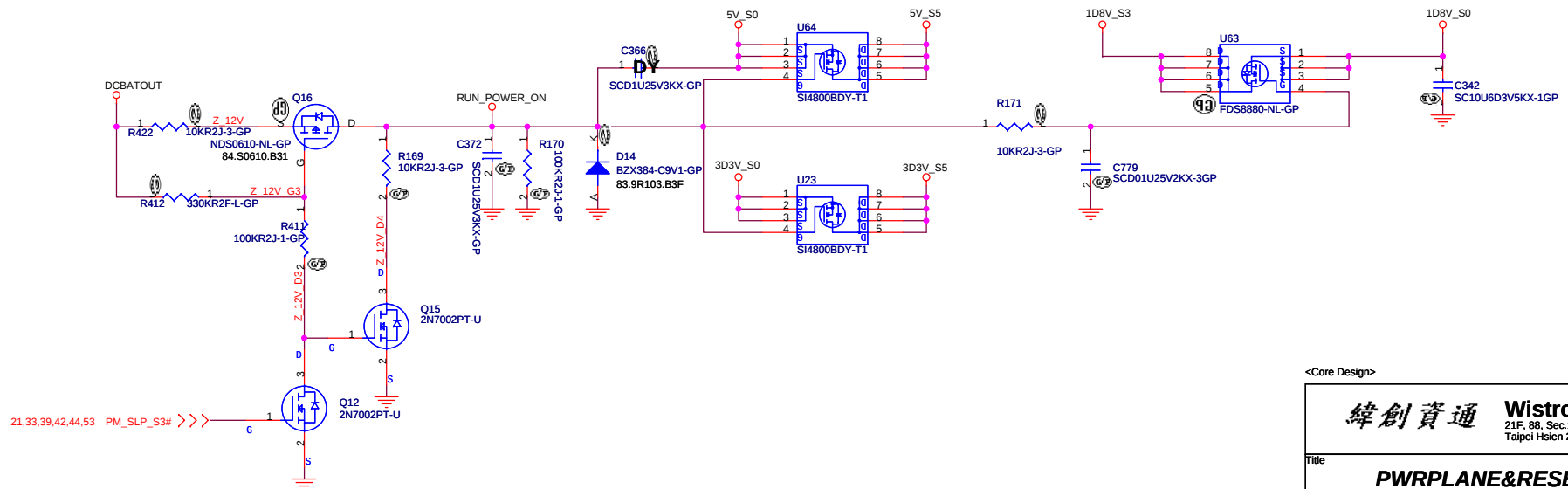


<Core Design>

緯創資通 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title		
DC to DC 1D5V / 0D9V / 1D25V		
Size A3	Document Number	Rev
	Hawke-Intel	-1
Date: Sunday, September 09, 2007	Sheet 44 of 57	



Run Power



<Core Design>

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

PWRPLANE&RESETLOGIC

Size
A3

Document Number

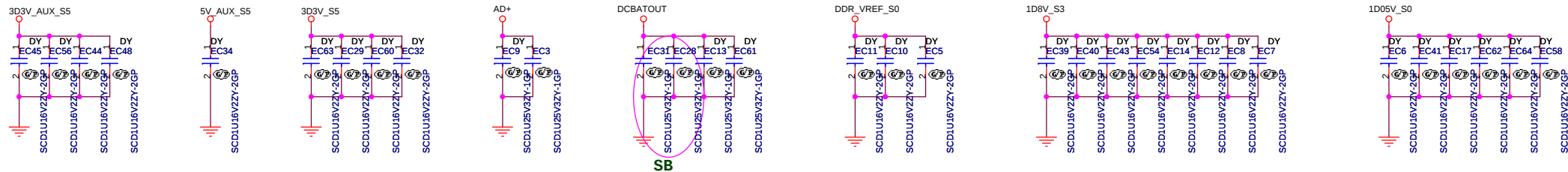
Hawke-Intel

Rev

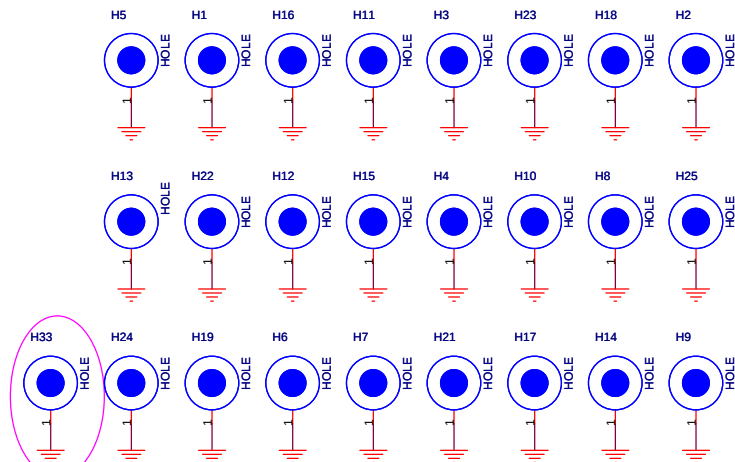
-1

Date: Sunday, September 09, 2007

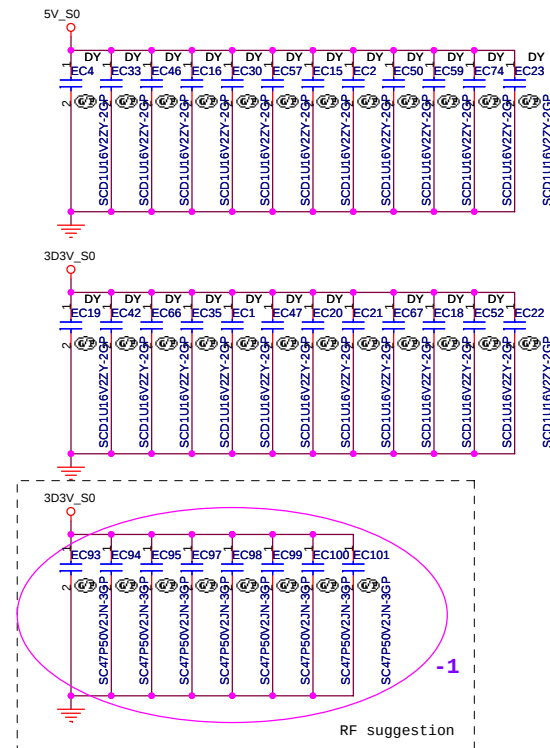
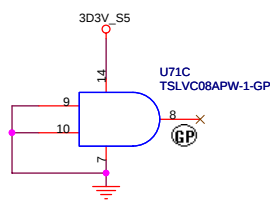
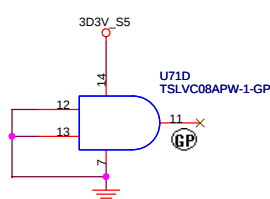
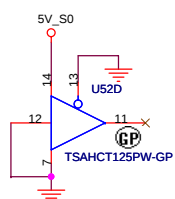
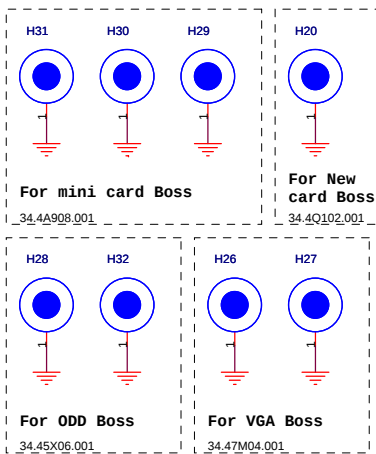
Sheet 45 of 57



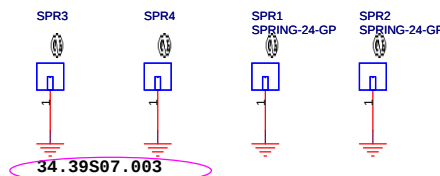
SB



SB



RF suggestion

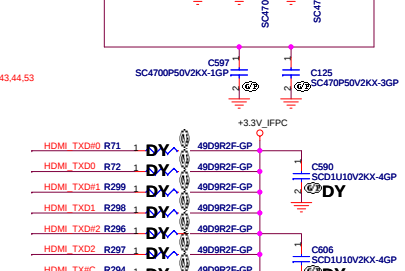
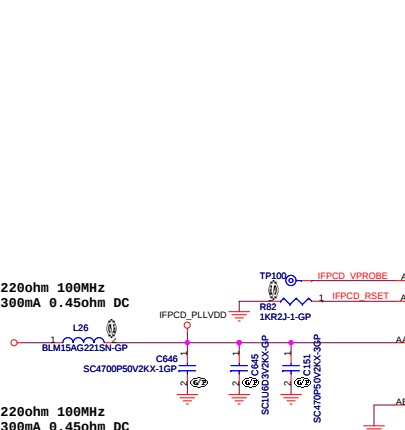
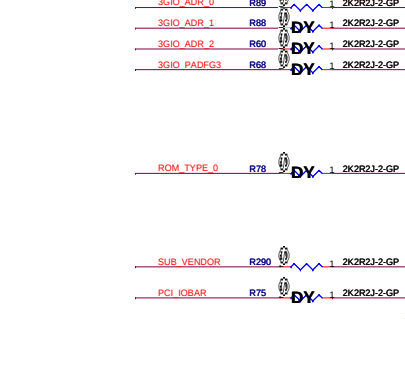
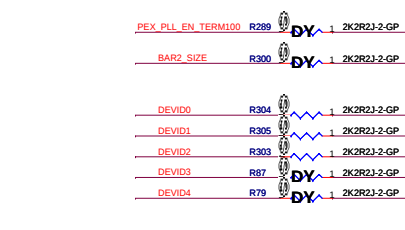
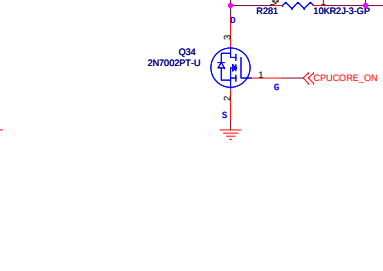
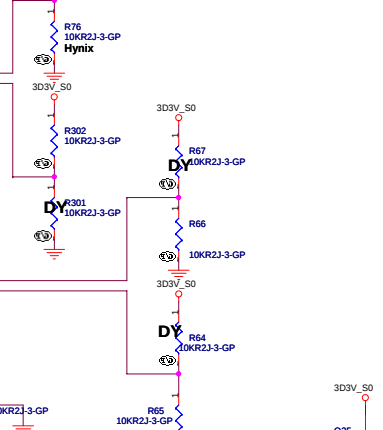
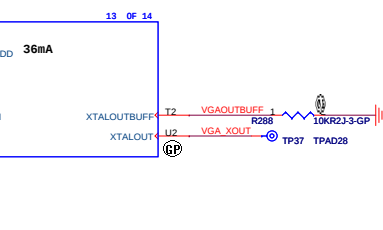
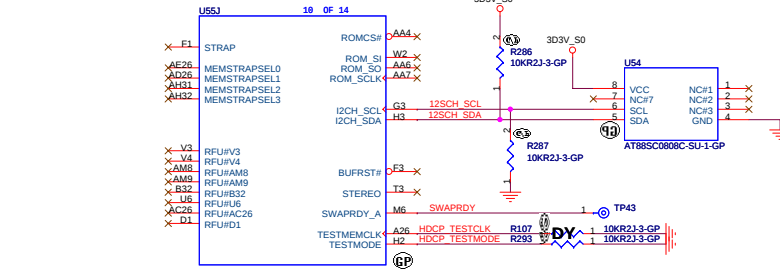
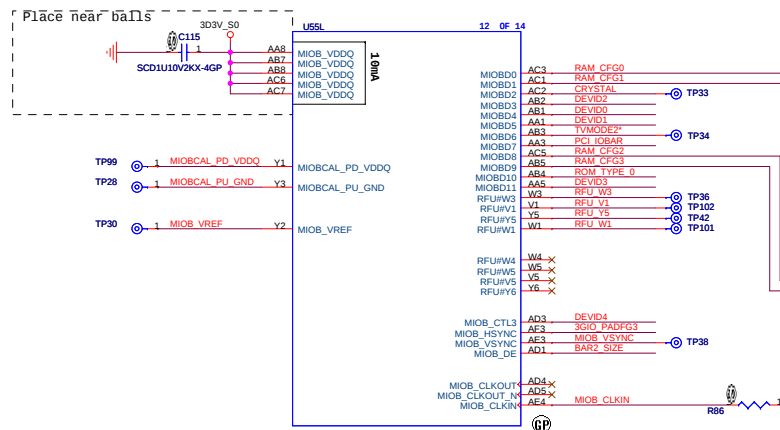
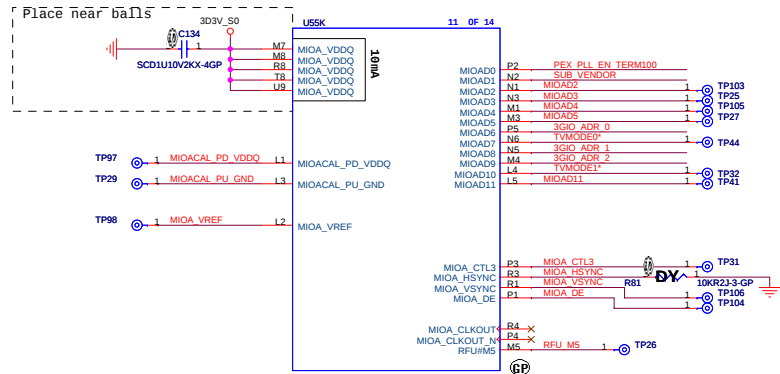
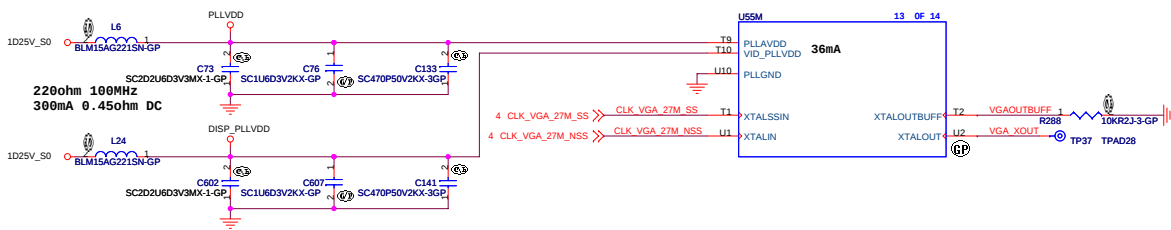


34.39S07.003

SB







PEX_PLL_EN_TERM	BAR2_SIZE
0 Enable	0 32 Mb
1 Disable	1 16 Mb

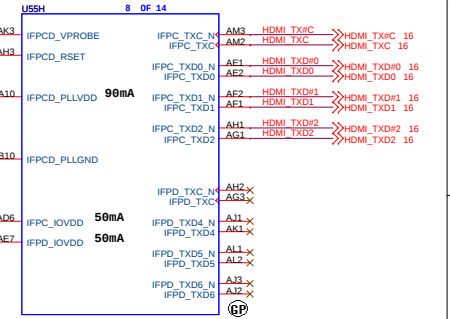
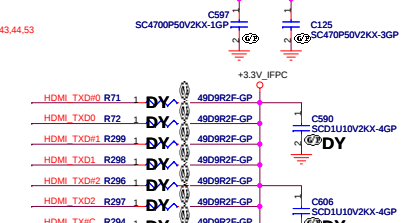
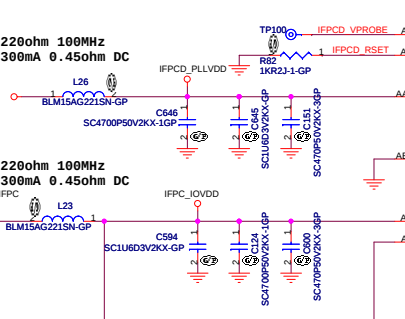
DEVID0	DEVID1	DEVID2	DEVID3	DEVID4	DEVID5
G726LM	1	1	1	0	0
G72M	1	1	0	0	0
G72MV	1	0	1	1	1
G86-GS	0	0	1	1	1
G84-GS					

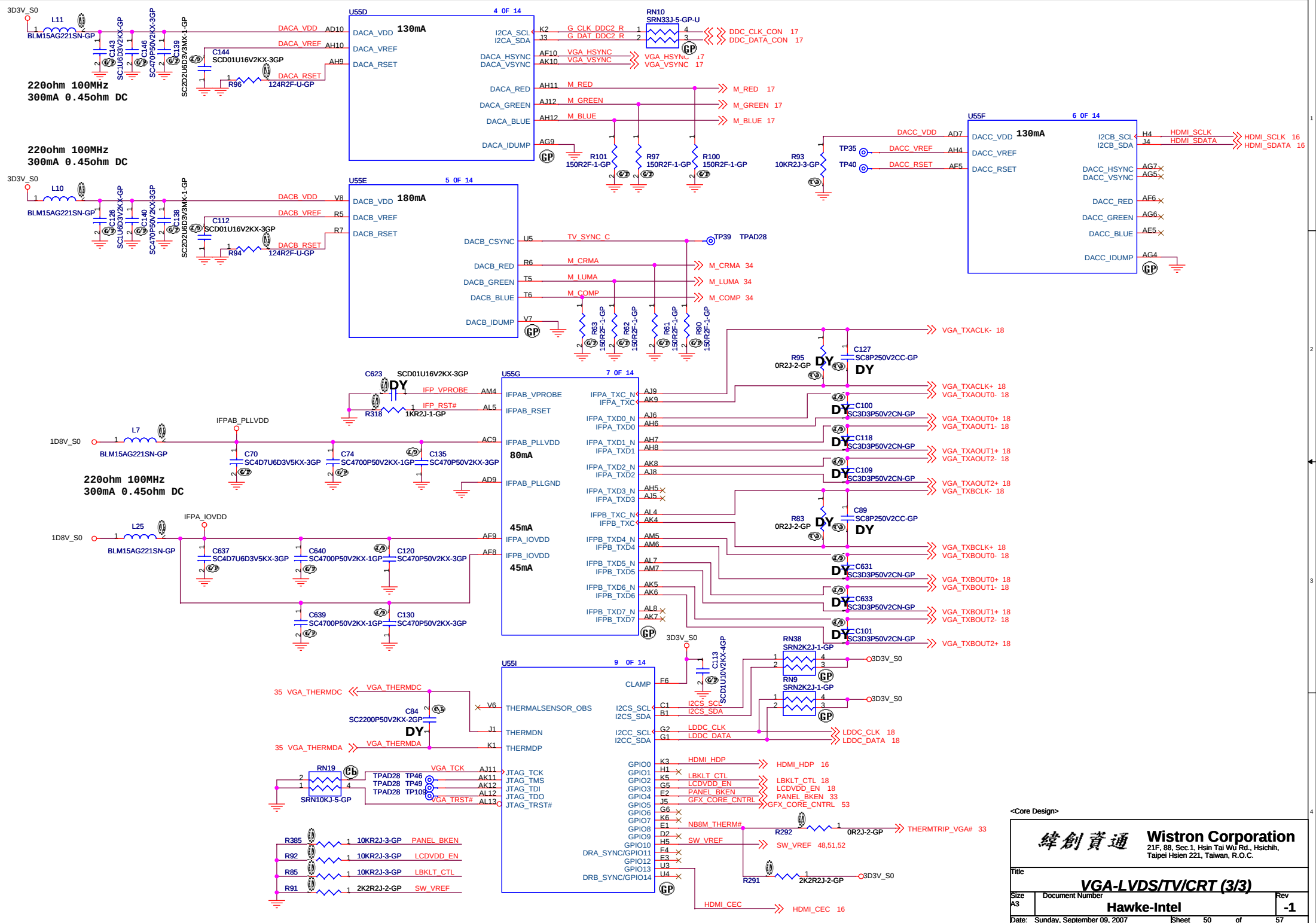
3GIO_PADCFG[3:0]	Notes
0000	Desktop (Default)
0001	Mobile1 Recommended for NV43/NV44/G7x
0010	Mobile2 NV42
0011	Mobile3
0100	Reserved
0101...1110	Reserved
1111	Reserved

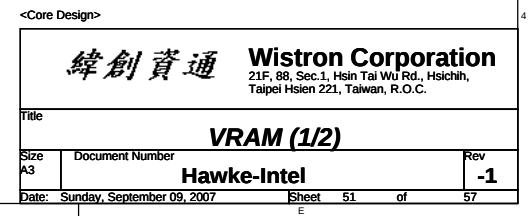
ROMTYPE[1:0]	
00 Parallel	
01 Serial	
10 Reserved	
11 LPC	

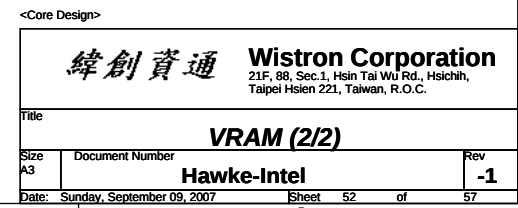
SUB_VENDOR	PCI_IOBAR
0 No video BIOS ROM	0 Disabled
1 BIOS ROM is present	1 Enabled

RAM_CF6[3:0]	
MIOBD0	Infineon 8MX32 DDR3 1.8V 0101
MIOBD1	Hynix 8MX32 DDR3 1.8V 0111
MIOBD2	Samsung 8MX32 DDR3 1.8V 0110
MIOBD3	Infineon 16MX32 DDR3 1.8V 0001
MIOBD4	Hynix 16MX32 DDR3 1.8V 0010
MIOBD5	Samsung 16MX32 DDR3 1.8V 0011

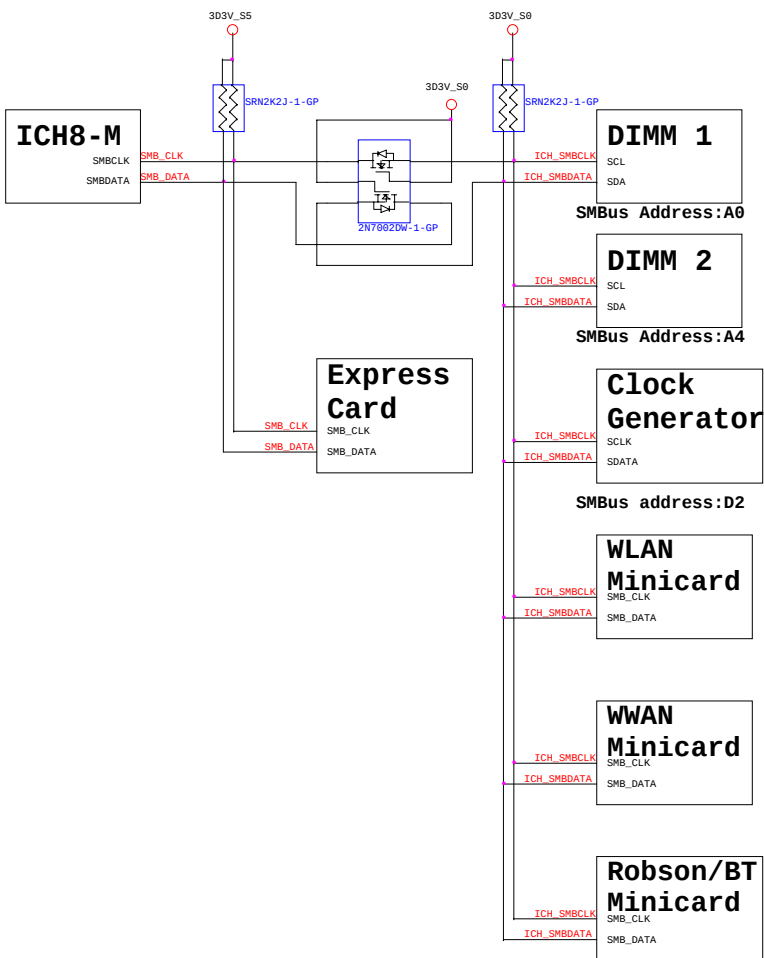




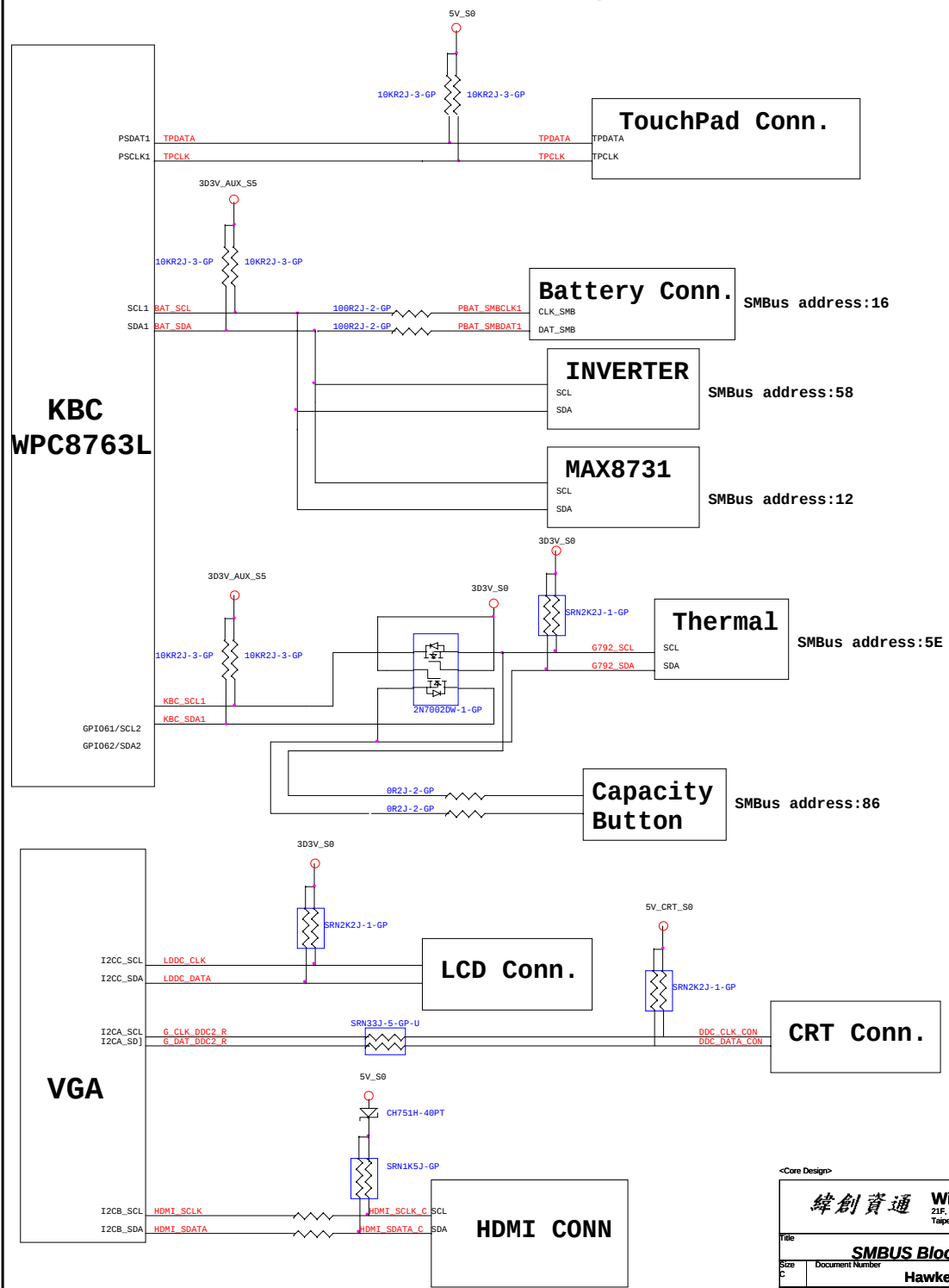




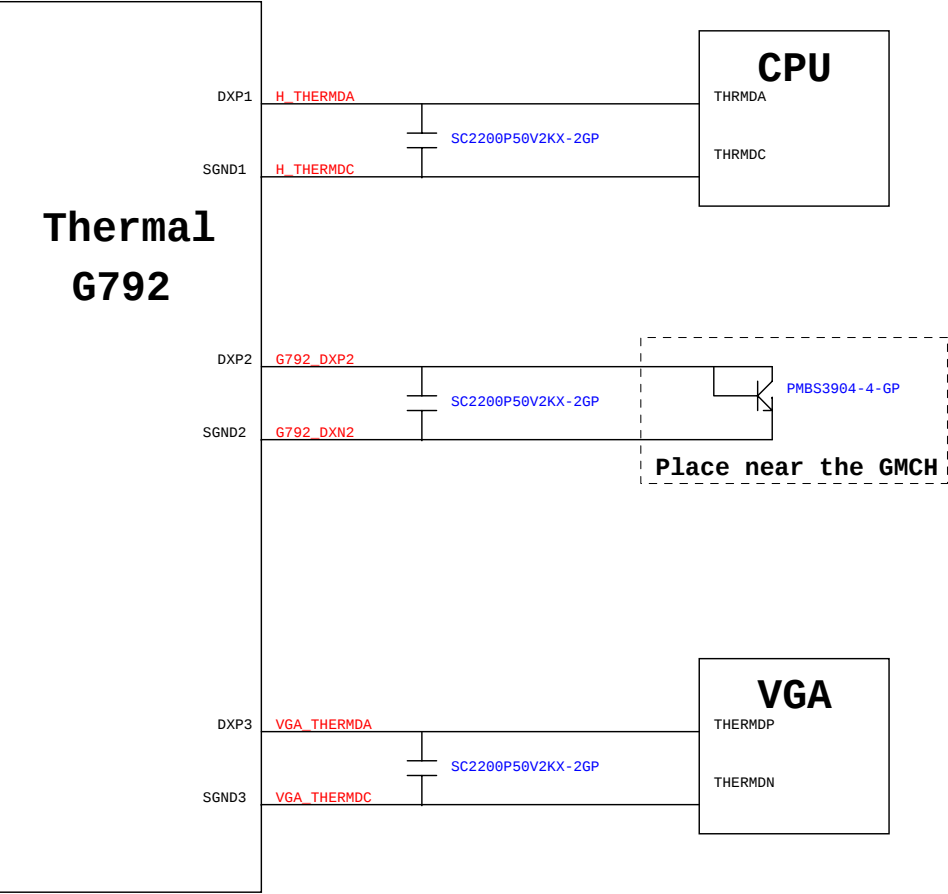
ICH8 SMBus Block Diagram



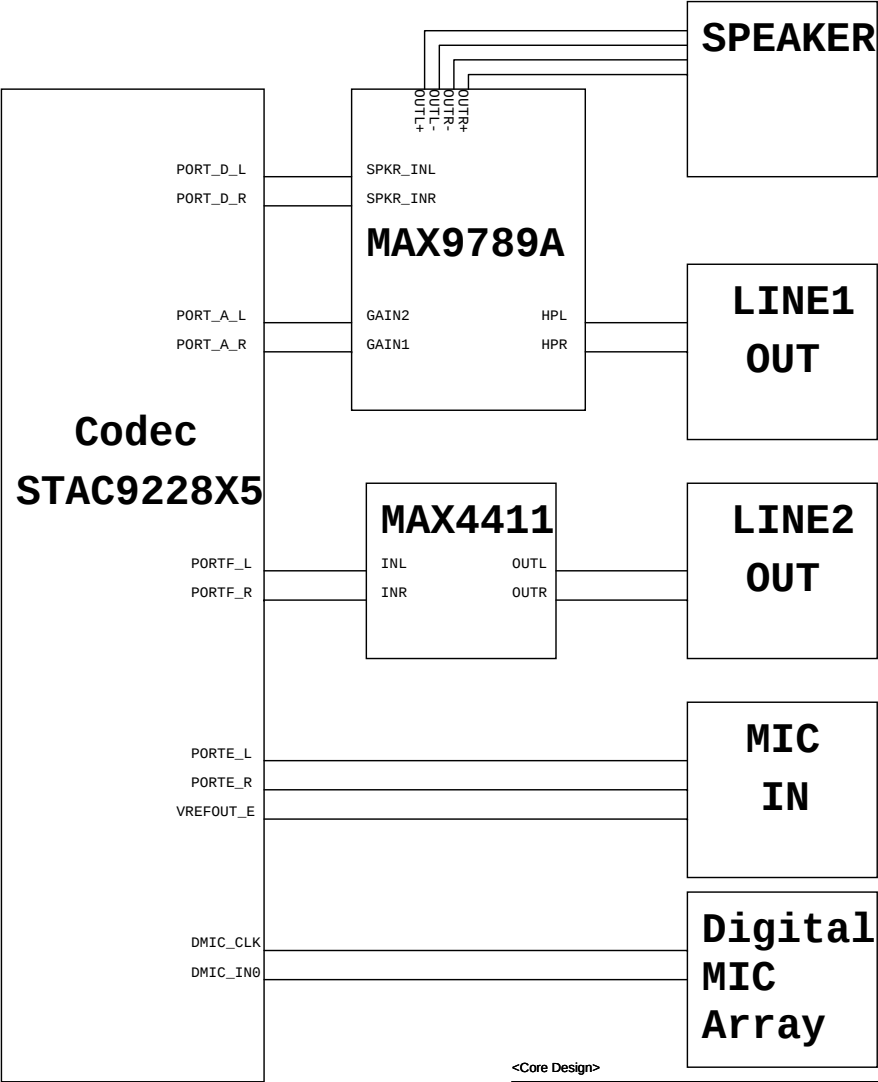
KBC SMBus Block Diagram



Thermal Block Diagram

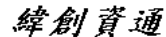


Audio Block Diagram



DATE	VERSION	ITEM	PAGE	Modify List	Issue Description	OWNER
2007/07/06	X00 to X01	1	4	Changed R431 from 10K ohm to 2.2K ohm.	Follow M08 design.	EE
		2	4	Changed X4's CL from 20pF to 10pF and changed C392 and C399 from 27pF to 12pF.	By the Xtal vendor's FAE suggestion.	EE
		3	4	Changed RN27, RN28, RN29 and RN31 from 0 ohm to 22 ohm.	To solved these clock signals' Slew Rate are over spec.	EE
		4	18	Changed LVDS connector from 42-pin to 40-pin.	By ME suggestion.	ME
		5	18,33	Connected the LCD1 pin 3 to GND and connected pin 6 to WPC8763's GPIO05 (pin 108 of U17) with 10K ohm pull up to 3D3V_AUX_S5.	Supported the LCD cable PAID.	EE
		6	18	Added EC75-EC78 near CAMERA1.	By EMC team suggestion.	EMC
		7	20	Change C354 and C355 from 15pF to 12pF and changed X1 package from DMX26S to SM-14J.	By the Xtal vendor's FAE suggestion.	EE
		8	21	Added R526 10K ohm between GPIO26 and 3D3V_S0, removed R404.	To solved 3D3V_S0 has leakage when S3 and S5.	EE
		9	21	Added the reserved Q47, D31, R530, R531 and R532.	For test EC_RMRST#_R circuit.	EE
		10	21	Changed R442 from 22.6 ohm to 20 ohm.	To sloved the left side USB ports and Camera USB's eye diagram fail.	EE
		11	23	Changed HDD connector.	By ME suggestion.	ME
		12	25	Changed 1394 connector.	To used reverse type by ME suggestion.	ME
		13	25	Changed X5's CL from 20pF to 12pF.	By the Xtal vendor's FAE suggestion.	EE
		14	25	Removed R466, U26, R192 and D19, and connected the net MC_PWR_CTRL_0 to U25 pin 4.	For these materials are no used.	EE
		15	25	Populated C887, C888 and C894-C896.	By EMC team suggestion.	EMC
		16	26	Changed C387 and C390 from 27pF to 12pF.	By the Xtal vendor's FAE suggestion.	EE
		17	27	Changed RJ1 connector.	By ME suggestion.	ME
		18	30	Changed U61 from 8Mbits to 16Mbits SPI ROM.	By customer requirement.	EE
		19	30	Added EC79-EC82 near CAP1.	By EMC team suggestion.	EMC
		20	30	Added EC83-EC88 near BT1.	By EMC team suggestion.	EMC
		21	30	Added EC90-EC91 near CN2 (Biometric).	By EMC team suggestion.	EMC
		22	31	Changed C880 and C881 from 0402 size to 0603 size.	Follow Thurman design.	EE
		23	32	Swaped the nets AUD_HP1_OUT_R1, AUD_HP1_OUT_L1 with AUD_AMP_GAIN1, AUD_AMP_GAIN2.	To sloved the HP1 hadn't output.	EE
		24	32	Changed R211 and R212 from 100K ohm to 10M ohm.	To sloved the AUD_HP1_EN and AUD_HP2_EN volatge level lower than 2V.	EE
		25	33	De-pop R396 and populated R395.	To changed the MB version id to SB.	EE
		26	33	Changed R391 and R405 from 10K ohm to 100K ohm.	To sloved the INSTANT_BTN# and SNIFFER_PWR_SW# can't work.	EE
		27	33	Added R527 100K ohm between WLAN/BT_BTN# and 3D3V_AUX_S5.	To sloved the WLAN/BT_BTN# can't work.	EE
		28	33	Changed X2 package from DMX26S to SM-14J.	By the Xtal vendor's FAE suggestion.	EE
		29	33,36	Changed KB1 from 25-pin to 27-pin connector, connected the KB1 pin 27 to GND and connected pin 26 to WPC8763's GPI92 (pin 99 of U17) with 10K ohm pull up to 3D3V_AUX_S5.	Supported the KB cable PAID.	ME,EE
		30	33	Changed R408 and R389 from 10K ohm to 4.7K ohm.	By Vendor's FAE suggestion.	EE
		31	35	Changed FAN1 from 4-pin to 3-pin connector.	By ME suggestion.	ME
		32	36	Added R534, Q48 and R535 off SATA_LED# and Q23.	Supported the HDD LED is dim when sinffer switch press.	EE
		33	36	Connected LED2 pin A from 5V_S0 to 5V_S5.	To sloved the Power LED can't breath when system enter S3.	EE
		34	38	Changed C530 and C531 from 1206 size to 1210 size and populated C7.	To solved noise when battery full load.	Power
		35	39	Changed R477 from 12.1K ohm to 13.3K ohm and changed R468 from 12.1K ohm to 11.8K ohm.	To adjust 3.3V and 5V current limit by power team suggestion.	Power
		36	40	Changed R7 from 12.7K ohm to 11.8K ohm and changed R468 from 3.24K ohm to 3.65K ohm.	To adjust CPU Vcore current limit by power team suggestion.	Power
		37	42	Changed R135 from 12.1K ohm to 11K ohm .	To adjust 1.05V current limit by power team suggestion.	Power
		38	43	Populated C529.	By EMC team suggestion.	EMC
		39	46	Added more one hole H33.	By EMC team suggestion.	EMC
		40	46	Populated EC28 and EC31.	By EMC team suggestion.	EMC
		41	47	Added C900, C901, C904 10uF and TC26 100uF.	To sloved VGA Vcore had OVP when run 3Dmark.	Power
		42	53	Changed R135 from 12.1K ohm to 10.5K ohm .	To adjust CPU Vcore current limit by power team suggestion.	Power
		43	53	Added EC89 0.1uF between DCBATOUT and GND.	By EMC team suggestion.	EMC

<Core Design>

 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title	
HISTORY from X00 to X01	
Size A3	Document Number Hawke-Intel
Date: Sunday, September 09, 2007	Sheet 56 of 57
Rev -1	

DATE	VERSION	ITEM	PAGE	Modify List	Issue Description	OWNER
2007/08/17	X01 to X02	1	4	Changed U22 from ICS 9LPRS365BKLT to Realtek RTM875M-606-LF.	Changed clock gen symbol from ICS 9LPRS365BKLT to Realtek RTM875M-606-LF.	EE
		2	15	Changed HDMI power rail from +5V_HDMI to 5V_S0.	Follow Thurman design.	EE
		3	17	Populated D4, D5, D6, D7 and D8.	By NV GPU ESD requirement.	EMC
		4	17	Changed L1, L2 and L4 from BLM18BA100SN1 to BLM18BB470SN1	To solve the ring on RGB singnal.	EE
		5	18, 33	Added D32, connected pin 1 to LCDVDD_TST_EN, pin 2 to LCDVDD_EN and pin 3 to ENVDD. Changed R276 from 0 to 100k ohm and changed R276.1 to GND	Added LCDVDD_TST_EN from U17.27 to control U53.3	EE
		6	18	Disconnted LCD1 pin 3 and pin 10	To prevent the power short to GND.	EE
		7	21	Added R542 for ECSCI# need to pull up 3D3V_S0	To solve one of CPU core always loading 100%.	EE
		8	27	Added EC92 22pF between NEWCARD_CLKREQ# and GND	By EMC team suggestion.	EE
		9	27	Added note for transformer source part number.	By EMC team suggestion.	EE
		10	29	1.Changed D20 to U73 for Bluetooth Action circuit. 2.Reserved U73, R193 and R195, populated R194.	1.It can be used both BT module and BT mini-card. 2.Keep BT module now.	EE
		11	29, 33	Connect MINI2 pin 20 to U17.24 (GP047 of KBC).	Changed WWAN enable WiFi RF controlled by another GPIO pin (U17.24 is GP047 of KBC).	EE
		12	30, 33	Rename SNIFFER_YELLOW# to SNIFFER_YELLOW, SNIFFER_BLUE# to SNIFFER_BLUE.	These pins are High active.	EE
		13	30	Disconnted SNIFFER_BD1 pin 8 and CAP1 pin 7.	To prevent power short to GND.	EE
		14	30	Changed EC90 and EC91 from 22pF to MLVG0402220NV05BP.	By EMC team suggestion.	EMC
		15	32	Populated EC24, EC25, EC26 and EC27 and change to 1000pF.	By EMC team suggestion.	EMC
		16	32	Changed Q45 to U47 and added R543.	To add AUD_SPK_ENABLE# controlled by AMP_MUTE#.	EE
		17	32	Changed R197 from 0 ohm to 100K ohm and pull up to +5V_SPK_AMP, dispopulated R505 and populated R213.	To solve HP1, HP2 and Speaker have "BoBo" noisy when power on, off, enter S3.	EE
		18	33	Populated R396 and R398, dispopulated R395 and R399.	Change Board ID to version SC.	EE
		19	36	Populated Q48 and R534, dispopulated R535.	HDD LED should be dim when power on by Sniffer button.	EE
		20	36	Changed C275 and C276 from reserved 33pF to MLVG0402220NV05BP, and populated them	By EMC team suggestion.	EMC
		21	36	Changed KB EMI caps from 220pF to 180pF.	To solved the word has repeat symptom when key-in.	EE
		22	38	The U42 and U44 were swap the main source and 2nd source.	To prevented used A04468 that SI4800BDY 2nd source on charger H/S and L/S MOS.	EE
		23	39	Populated R485 and dispopulated R489.	To changed 3V and 5V PWM to Skip mode.	EE
		24	42, 43, 53	Changed C329, C566 and C272 rated voltage from 6.3V to 10V.	For derating issues by power team requirment.	EE
		25	43, 53	Change the U56 and U39 from 2nd source to main source, and swap the U38 and U58's the main source and 2nd source	To combined U39 and U56 material item of BOM with CPU H/S MOS (U4 and U35).	EE
		26	20	Changed C354 and C355 from 12pF to 8.2pF.	For Negative Resistance of X1 isn't enough.	EE
		27	33	Changed C350 and C351 from 15pF to 10pF.	For Negative Resistance of X2 isn't enough.	EE